



Product Technical Specification & Customer Design Guidelines

Q64 Wireless CPU[®]

Reference: **WA_DEV_Q64_PTS_001**

Revision: **003**

Date: **January 9, 2009**

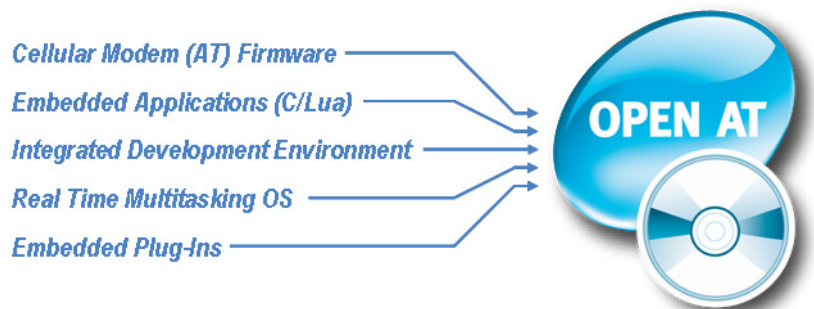


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Q64 Wireless CPU[®]

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Powered by the Wavecom Open AT[®] Software Suite

Document History

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001	February 6, 2008	Creation	
002	July 11, 2008	Updates	
003	January 9, 2009	Updates to sections §3.3.1, §3.15.1, §5.1, §7.13 and some minor changes	

Overview

This document defines and specifies the Q64 Wireless CPU[®], available in a GSM/GPRS Class 10 quad-band version.

Q64 Wireless CPU[®] is a variant of Wavecom Wireless Microprocessor[®] WMP100, which is pin to pin and functionally compatible with Wavecom Wireless CPU[®] GR64001.

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1 References

1.1 Reference Documents

For more details, several documents are referenced in this specification. The Wavecom documents references herein are provided in the Wavecom documentation package; the general reference documents which are not Wavecom owned are not provided in the documentation package.

1.1.1 Wavecom Reference Documentation

- [1] Wireless Microprocessor® WMP100 Technical Specification
(Ref: WM_DEV_WUP_PTS_004)
- [2] Wireless CPU® Q64 Hardware Differences between Q64 and GR64
(Ref: WA_DEV_Q64_PTS_002)
- [3] Integrator's Manual – GR64 GSM/GPRS Wireless CPU®
(Ref: WI_DEV_GR64_UGD_001)
- [4] AT Command Interface Guide for Open AT® Firmware v6.5
(Ref: WM_DEV_OAT_UGD_035)
- [5] Q64 software user guide
(Ref: WA_DEV_Q64_UGD_003)
- [6] AT Command Manual for GR64 and GS64 Wireless CPU®
(Ref: WI_DEV_Gx64_UGD_001)

1.1.2 General Reference Documentation

- [7] "I²C Bus Specification", Version 2.0, Philips Semiconductor 1998
- [8] ISO 7816-3 Standard

1.2 List of Abbreviations

Abbreviation Definition

AC	Alternative Current
ADC	Analog to Digital Converter
A/D	Analog to Digital conversion
AF	Audio-Frequency
AT	ATtention (prefix for modem commands)
AUX	AUXiliary
CAN	Controller Area Network
CB	Cell Broadcast
CEP	Circular Error Probable
CLK	CLock
CMOS	Complementary Metal Oxide Semiconductor
CS	Coding Scheme
CTS	Clear To Send
DAC	Digital to Analogue Converter
dB	Decibel
DC	Direct Current
DCD	Data Carrier Detect
DCE	Data Communication Equipment
DCS	Digital Cellular System
DR	Dynamic Range
DSR	Data Set Ready
DTE	Data Terminal Equipment
DTR	Data Terminal Ready
EFR	Enhanced Full Rate
E-GSM	Extended GSM
EMC	ElectroMagnetic Compatibility
EMI	ElectroMagnetic Interference
EMS	Enhanced Message Service
EN	ENable
ESD	ElectroStatic Discharges
FIFO	First In First Out

Abbreviation Definition

FR	Full Rate
FTA	Full Type Approval
GND	GrouND
GPI	General Purpose Input
GPC	General Purpose Connector
GPIO	General Purpose Input Output
GPO	General Purpose Output
GPRS	General Packet Radio Service
GPS	Global Positioning System
GSM	Global System for Mobile communications
HR	Half Rate
I/O	Input / Output
LED	Light Emitting Diode
LNA	Low Noise Amplifier
MAX	MAXimum
MIC	MICrophone
MIN	MINimum
MMS	Multimedia Message Service
MO	Mobile Originated
MT	Mobile Terminated
na	Not Applicable
NF	Noise Factor
NMEA	National Marine Electronics Association
NOM	NOMinal
NTC	Négative Temperature Coefficient
PA	Power Amplifier
Pa	Pascal (for speaker sound pressure measurements)
PBCCH	Packet Broadcast Control CHannel
PC	Personal Computer
PCB	Printed Circuit Board
PDA	Personal Digital Assistant
PFM	Power Frequency Modulation
PSM	Phase Shift Modulation
PWM	Pulse Width Modulation

Abbreviation Definition

RAM	Random Access Memory
RF	Radio Frequency
RFI	Radio Frequency Interference
RHCP	Right Hand Circular Polarization
RI	Ring Indicator
RST	ReSeT
RTC	Real Time Clock
RTCM	Radio Technical Commission for Maritime services
RTS	Request To Send
RX	Receive
SCL	Serial CLock
SDA	Serial DAta
SIM	Subscriber Identification Module
SMS	Short Message Service
SPI	Serial Peripheral Interface
SPL	Sound Pressure Level
SPK	SPEaKer
PSRAM	Pseudo Static RAM
TBC	To Be Confirmed
TDMA	Time Division Multiple Access
TP	Test Point
TVS	Transient Voltage Suppressor
TX	Transmit
TYP	TYPical
UART	Universal Asynchronous Receiver-Transmitter
USB	Universal Serial Bus
USSD	Unstructured Supplementary Services Data
VSWR	Voltage Standing Wave Ratio

2 General Description

2.1 General Information

The Q64 Wireless CPU® is a self-contained E-GSM/GPRS 900/1800 and 850/1900 quad-band Wireless CPU®, including the characteristics listed in the subsection below:

2.1.1 Overall Dimensions

- Length: 50 mm
- Width: 33 mm
- Thickness: 6.9 mm
- Weight: 11.6 g

2.1.2 Environment and Mechanics

- Green policy: Restriction of Hazardous Substances in Electrical and Electronic Equipment (RoHS) compliant
- Complete shielding

The Q64 Wireless CPU® is compliant with RoHS Directive 2002/95/EC, which sets limits for the use of certain restricted hazardous substances. This directive states that “from 1st July 2006, new electrical and electronic equipment sold on the market does not contain lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB), and polybrominated diphenyl ethers (PBDE)”.

2.1.3 GSM/GPRS Features

- 2-Watt EGSM 900/GSM 850 radio section running under 3.6 volts
- 1-Watt GSM1800/1900 radio section running under 3.6 volts
- Hardware GPRS class 10 capable

2.1.4 Interfaces

- Digital section running under 2.8 volts
- 3V/1V8 SIM interface
- Power supply
- Serial links (UART)
- Analogue audio
- ADC
- PCM digital audio
- USB 2.0 slave
- I2C Serial buses
- PWM (BUZZER)
- GPIOs

2.1.5 Operating System

- Real Time Clock (RTC) with calendar
- Echo Cancellation + noise reduction (quadri codec)
- Full GSM or GSM/GPRS Operating System stack

2.1.6 Connection Interfaces

The Q64 Wireless CPU® has two external connections:

- One for RF circuit:
 - MMCX connector
- One for baseband signals:
 - 60-pin I/O connector

2.2 Functional Description

The global architecture of Q64 Wireless CPU® is described below:

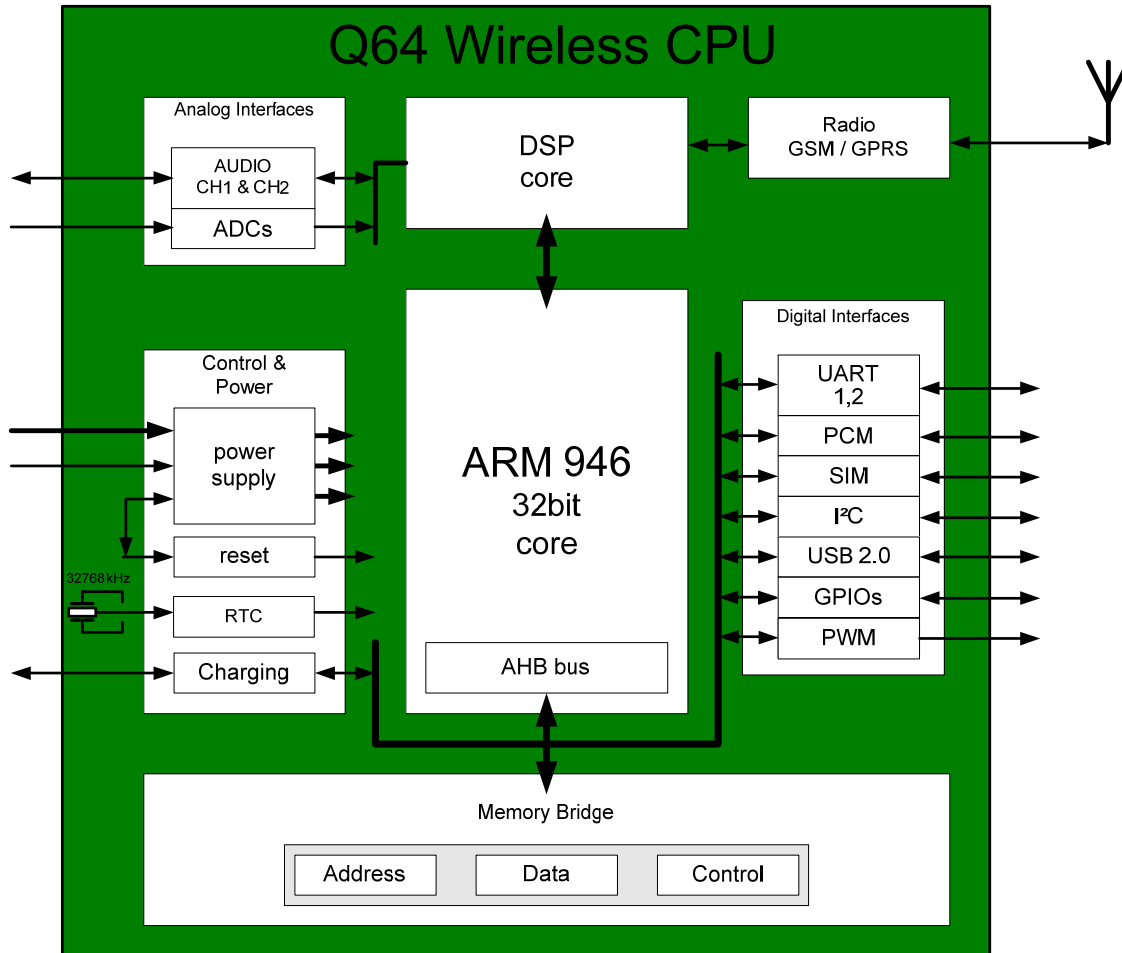


Figure 1 : Functional architecture

2.2.1 RF Functionalities

The Radio Frequency (RF) range complies with the Phase II EGSM 900/DCS 1800 and GSM 850/PCS 1900 recommendation. The frequencies are listed in the table below:

	Transmit band (Tx)	Receive band (Rx)
GSM 850	824 to 849 MHz	869 to 894 MHz
E-GSM 900	880 to 915 MHz	925 to 960 MHz
DCS 1800	1710 to 1785 MHz	1805 to 1880 MHz
PCS 1900	1850 to 1910 MHz	1930 to 1990 MHz

The Q64 Wireless CPU® is designed to be used with Wavecom WMP100 Wireless Microprocessor®. The Radio Frequency (RF) part is based on a specific quad-band chip with a:

- Digital low-IF receiver
- Quad-band LNA (Low Noise Amplifier)
- Offset PLL (Phase Locked Loop) transmitter
- Frequency synthesizer
- Digitally controlled crystal oscillator (DCXO)
- Tx/Rx FEM (Front-End Module) for quad-band GSM/GPRS

2.3 Operating System

The Q64 Wireless CPU® is designed to integrate various types of specific process applications such as telemetry, multimedia, automotive known as vertical applications.

The Operating System provides a set of AT commands to control the Wireless CPU®. With this standard Operating System, some interfaces of the Wireless CPU® are not available, since they are dependent on the peripheral devices connected to the Wireless CPU®.

The Operating System is Open AT® compliant.

2.4 Software Description

The software package of Q64, Open AT® Software Suite v1.0 / v2.0, includes:

- An Open AT® Firmware v6.5 which drives the Q64 and offer an AT command interface over a serial port or USB.
- An Open AT® Operating System (OS) v5.0 which runs various types of applications (telemetry, multimedia, automotive...)
- An Open AT® Integrated Development Environment (IDE) which builds and debugs applications over the Open AT® Operating System

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- Several other Open AT[®] plug-in softwares are able to run over the Open AT[®] Operating System.
- A “GR plug-in” software that provides software compatibility with GR64 Wireless CPU[®], in terms of AT commands and system operation. It is specifically designed for GR64 Wireless CPU[®] compatibility.

3 Interfaces

3.1 General Interfaces

Every hardware interface of the Q64 can be accessed with the Q64 development kit, or GR64 Tina or UMA Board.

The available interfaces are described in the table below:

Chapter	Name	Driven by AT commands	Driven by Open AT®
3.6	Main Serial Link	X	X
3.7	Auxiliary Serial Link	X	X
3.8	SIM Interface	X	X
3.9	General Purpose IO	X	X
3.5	Serial Interface (I2C Bus)		X
3.10	Analog to Digital Converter	X	X
3.12	PWM / Buzzer Output	X	X
3.13	Battery charging interface	X	X
3.17	VRTC (Backup Battery)	X	X
3.18	LED signal	X	X
3.19	Digital Audio Interface (PCM)	X	X
3.20	USB 2.0 Interface	X	X

3.2 Power Supply

3.2.1 Power Supply Description

The power supply is one of the key issues in the design of a GSM terminal.

Due to the burst emission mode used in GSM/GPRS, the power supply should deliver high current peaks in a short time. During the peaks, the ripple (U_{ripp}) on the supply voltage must not exceed a certain limit (see Table 1 Power supply voltage "Power Supply Voltage").

- In communication mode, a GSM/GPRS class 2 terminal emits $577\mu\text{s}$ radio bursts every 4.615ms (see Figure 2 below).

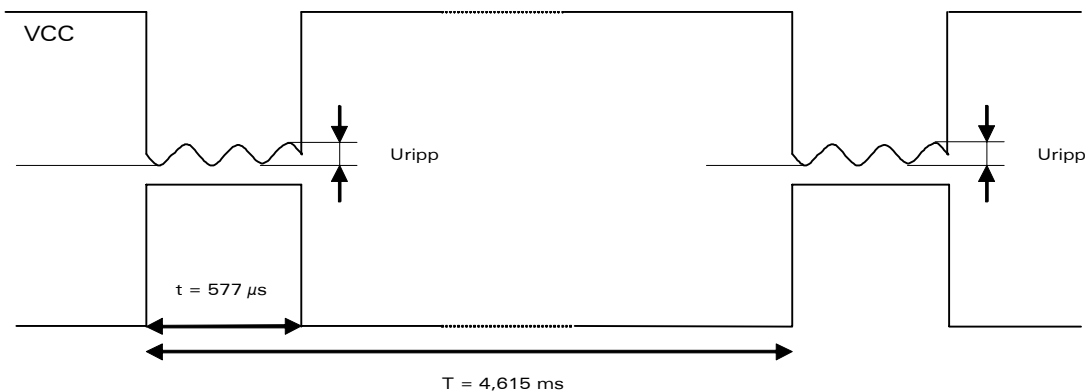


Figure 2: Power supply during burst emission

- In communication mode, a GPRS class 10 terminal emits $1154\mu\text{s}$ radio bursts every 4.615ms .

The VCC power supply input is only available for Q64 Wireless CPU®.

VCC:

- Directly supplies the RF components with 3.6V . It is essential to keep a minimum voltage ripple at this connection in order to avoid any phase error.

The RF Power Amplifier current (1.5A peak in GSM /GPRS mode) flows with a ratio of:

- $1/8$ of the time (around $577\mu\text{s}$ every 4.615ms for GSM /GPRS cl. 2) and
- $2/8$ of the time (around $1154\mu\text{s}$ every 4.615ms for GSM /GPRS cl. 10).

The rising time is around $10\mu\text{s}$.

- Is internally used to provide, via several regulators, the supply required for the baseband signals.

3.2.2 Electrical Characteristics

Input power supply voltage

	V _{MIN}	V _{NOM}		V _{MAX}	I _{MAX}	Ripple max (U _{ripp})
VCC ^{1,2}	3.2	3.6		4.8	1.8 A	10mV

Table 1 Power supply voltage

- (1): This value must be guaranteed during the burst (with 1.5A Peak in GSM or GPRS mode)
 (2): Maximum operating Voltage Stationary Wave Ratio (VSWR) 2:1

When powering the WMP100 with a battery, the total impedance (battery + protections + PCB) should be <150 mΩ.

3.2.3 Power Supply Pin-out

Power supply pin-out

Signal	Pin number
VCC	1,3,5,7,9
GND	2,4,6,8,10,12

3.3 Power Consumption

Power consumption depends on the configuration. Therefore, the following consumption values are given for each mode, RF band and type of software used (with or without an Open AT[®] application).

Note: The following information is provided assuming a 50 Ω RF output.

The following consumption values were obtained by performing measurements on Q64 samples at a temperature of 25° C.

Three VCC values are used to measure the consumption, VCC_{MIN} (3.2V), VCC_{MAX} (4.8V) and VCC_{TYP} (3.6V).

The average current is given for the three VCC values and the peak current given is the maximum current peak measured with the three VCC voltages.

For more detailed descriptions of the operating modes, (refer to the document [4] AT Command Interface Guide for Open AT[®] Firmware v6.5).

For more information about the consumption measurement procedure, refer to section 4.

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3.3.1 Power Consumption without Open AT® Processing

The following measurements are relevant when no processing is required by the Open AT® application:

Either there is no Open AT® application or the Open AT® application is disabled

Power consumption without Open AT® application								
Operating mode	Parameters		I _{MIN} average VBATT=4,8V	I _{NOM} average VBATT=3,6V	I _{MAX} average VBATT=3,2V	I _{MAX} peak	unit	
Alarm Mode			27	19	17	N/A	µA	
Fast Idle Mode	Paging 9 (Rx burst occurrence ~2s)		16.4	17.6	18.5	160 _{RX}	mA	
	Paging 2 (Rx burst occurrence ~0,5s)		17.8	19.2	20.1	160 _{RX}	mA	
Slow Idle Mode¹	Paging 9 (Rx burst occurrence ~2s)		2.7	2.6	2.6	160 _{RX}	mA	
	Paging 2 (Rx burst occurrence ~0,5s)		5.3	5.4	5.6	160 _{RX}	mA	
Fast Standby Mode			32.1	38.1	42.4	80	mA	
Slow Standby Mode			2.1	1.9	1.8	80	mA	
Connected Mode	850/900 MHz	PCL5 (TX power 33dBm)	206/206	215/214	221/219	1500 _{TX}	mA	
		PCL19 (TX power 5dBm)	83/84	91/91	95/95	270 _{TX}	mA	
	1800/1900 MHz	PCL0 (TX power 30dBm)	147/154	156/164	160/169	900 _{TX}	mA	
		PCL15 (TX power 0dBm)	80/80	87/88	91/92	250 _{TX}	mA	
GPRS	Transfer Mode class 8 (4Rx/1Tx)	850/900 MHz	Gam.3 (TX power 33dBm)	197/197	206/205	211/210	1500 _{TX}	mA
			Gam.17 (TX power 5dBm)	79/80	86/87	90/91	270 _{TX}	mA
		1800/1900 MHz	Gam.3 (TX power 30dBm)	141/147	149/157	153/162	900 _{TX}	mA
			Gam.18 (TX power 0dBm)	76/76	83/83	87/87	250 _{TX}	mA
	Transfer Mode class 10 (3Rx/2Tx)	850/900 MHz	Gam.3 (TX power 33dBm)	354/353	365/362	372/370	1500 _{TX}	mA
			Gam.17 (TX power 5dBm)	121/114	116/122	125/126	270 _{TX}	mA
		1800/1900 MHz	Gam.3 (TX power 30dBm)	238/250	248/264	253/271	900 _{TX}	mA
			Gam.18 (TX power 0dBm)	106/107	114/115	118/119	250 _{TX}	mA

_{TX} means that the current peak is the RF transmission burst (Tx burst)

_{RX} means that the current peak is the RF reception burst (Rx burst)

¹**Fast Idle Mode** the signal of DTR1 (pin 37) is at high level.

²**Slow Idle Mode** consumption depends on the SIM card used. Some SIM cards respond faster than others; The longer the response time is, the higher the consumption is.

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3.3.2 Power Consumption with a Dhrystone Open AT® Application

The Open AT® application used is the Dhrystone application. The following consumption results are measured during the Dhrystone application run. The two tables are respectively for the CPU clock programmed at 26MHz and 104MHz.

Power consumption with Dhrystone Open AT® application@26MHz								
Operating mode	Parameters		I _{MIN} average VBATT=4,8 V	I _{NOM} average VBATT=3,6 V	I _{MAX} average VBATT=3,2 V	I _{MAX} peak	unit	
Alarm Mode			N/A	N/A	N/A	N/A		
Fast Idle Mode	Paging 9 (Rx burst occurrence ~2s)		33	40	42	180 _{RX}	mA	
	Paging 2 (Rx burst occurrence ~0,5s)		34	39	43	180 _{RX}	mA	
Slow Idle Mode¹	Paging 9 (Rx burst occurrence ~2s)		N/A	N/A	N/A	N/A		
	Paging 2 (Rx burst occurrence ~0,5s)		N/A	N/A	N/A	N/A		
Fast Standby Mode			33	39	43	60	mA	
Slow Standby Mode			N/A	N/A	N/A	N/A		
Connected Mode	850/900 MHz	PCL5 (TX power 33dBm)	202 / 208	214 / 218	219 / 224	1440 _{TX}	mA	
		PCL19 (TX power 5dBm)	84 / 84	92 / 92	96 / 96	270 _{TX}	mA	
	1800/1900 MHz	PCL0 (TX power 30dBm)	148 / 161	157 / 164	161 / 170	260 _{TX}	mA	
		PCL15 (TX power 0dBm)	80 / 81	88 / 89	92 / 93	230 _{TX}	mA	
GPRS	Transfer Mode class 8 (4Rx/1Tx)	850/900 MHz	Gam.3 (TX power 33dBm)	195 / 181	195 / 208	215 / 214	1420 _{TX}	mA
			Gam.17 (TX power 5dBm)	80 / 80	87 / 88	91 / 92	240 _{TX}	mA
		1800/1900 MHz	Gam.3 (TX power 30dBm)	141 / 148	150 / 157	154 / 163	930 _{TX}	mA
			Gam.18 (TX power 0dBm)	76 / 77	84 / 84	87 / 88	210 _{TX}	mA
	Transfer Mode class 10 (3Rx/2Tx)	850/900 MHz	Gam.3 (TX power 33dBm)	350 / 358	361 / 369	368 / 378	1460 _{TX}	mA
			Gam.17 (TX power 5dBm)	116 / 115	119 / 123	126 / 127	270 _{TX}	mA
		1800/1900 MHz	Gam.3 (TX power 30dBm)	239 / 251	249 / 264	254 / 271	960 _{TX}	mA
			Gam.18 (TX power 0dBm)	106 / 109	115 / 116	119 / 120	260 _{TX}	mA

_{TX} means that the current peak is the RF transmission burst (Tx burst)

_{RX} means that the current peak is the RF reception burst (Rx burst)

*N/A: It does not mean that no Open AT® application is possible in this specific mode. That means that the specific Dhrystone Open AT® application cannot allow this specific mode. (This is a worst case for the consumption measurement)

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Power consumption with Dhrystone Open AT® application@104MHz								
Operating mode	Parameters		I _{MIN} average VBATT=4,8 V	I _{NOM} average VBATT=3,6 V	I _{MAX} average VBATT=3,2 V	I _{MAX} peak	unit	
Alarm Mode			N/A	N/A	N/A	N/A		
Fast Idle Mode	Paging 9 (Rx burst occurrence ~2s)		73	89	96	240 _{RX}	mA	
	Paging 2 (Rx burst occurrence ~0,5s)		72	88	96	240 _{RX}	mA	
Slow Idle Mode¹	Paging 9 (Rx burst occurrence ~2s)		N/A	N/A	N/A	N/A		
	Paging 2 (Rx burst occurrence ~0,5s)		N/A	N/A	N/A	N/A		
Fast Standby Mode			63	80	86	110	mA	
Slow Standby Mode			N/A	N/A	N/A	N/A		
Connected Mode	850/900 MHz	PCL5 (TX power 33dBm)	233 / 236	252 / 256	262 / 267	1550 _{TX}	mA	
		PCL19 (TX power 5dBm)	112 / 113	130 / 130	139 / 140	320 _{TX}	mA	
	1800/1900 MHz	PCL0 (TX power 30dBm)	176 / 183	195 / 202	205 / 209	990 _{TX}	mA	
		PCL15 (TX power 0dBm)	109 / 109	126 / 127	135 / 136	280 _{TX}	mA	
GPRS	Transfer Mode class 8 (4Rx/1Tx)	850/900 MHz	Gam.3 (TX power 33dBm)	223 / 227	241 / 245	251 / 253	1540 _{TX}	mA
			Gam.17 (TX power 5dBm)	108 / 108	124 / 125	133 / 134	290 _{TX}	mA
		1800/1900 MHz	Gam.3 (TX power 30dBm)	169 / 175	187 / 194	196 / 204	260 _{TX}	mA
			Gam.18 (TX power 0dBm)	104 / 105	121 / 122	130 / 130	980 _{TX}	mA
	Transfer Mode class 10 (3Rx/2Tx)	850/900 MHz	Gam.3 (TX power 33dBm)	378 / 385	398 / 408	410 / 419	1560 _{TX}	mA
			Gam.17 (TX power 5dBm)	141 / 143	159 / 160	168 / 169	320 _{TX}	mA
		1800/1900 MHz	Gam.3 (TX power 30dBm)	267 / 279	286 / 301	297 / 313	1000 _{TX}	mA
			Gam.18 (TX power 0dBm)	135 / 136	152 / 153	161 / 162	280 _{TX}	mA

T_X means that the current peak is the RF transmission burst (Tx burst)

R_X means that the current peak is the RF reception burst (Rx burst)

*N/A: That does not mean that no Open AT® application is possible in this specific mode. That means that the specific Dhrystone Open AT® application cannot allow this specific mode. (This is a worst case for the consumption measurement)

3.3.3 Consumption Waveform Samples

The consumption waveforms presented below are for an EGSM900 network configuration without the Open AT[®] Software Suite running on the Q64.

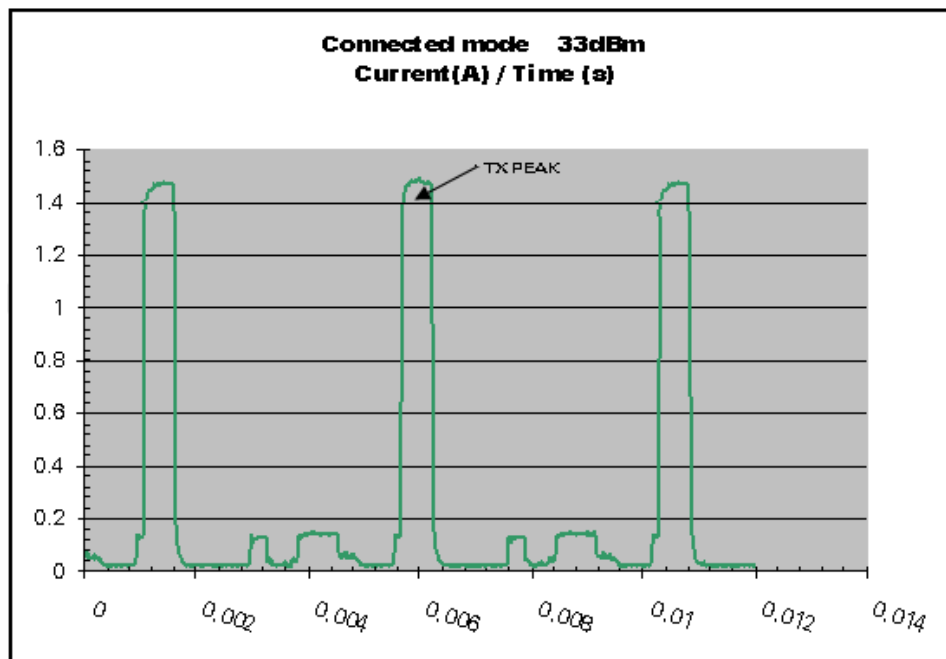
The usual VCC voltage is 3.6V.

Four significant operating mode consumption waveforms are described:

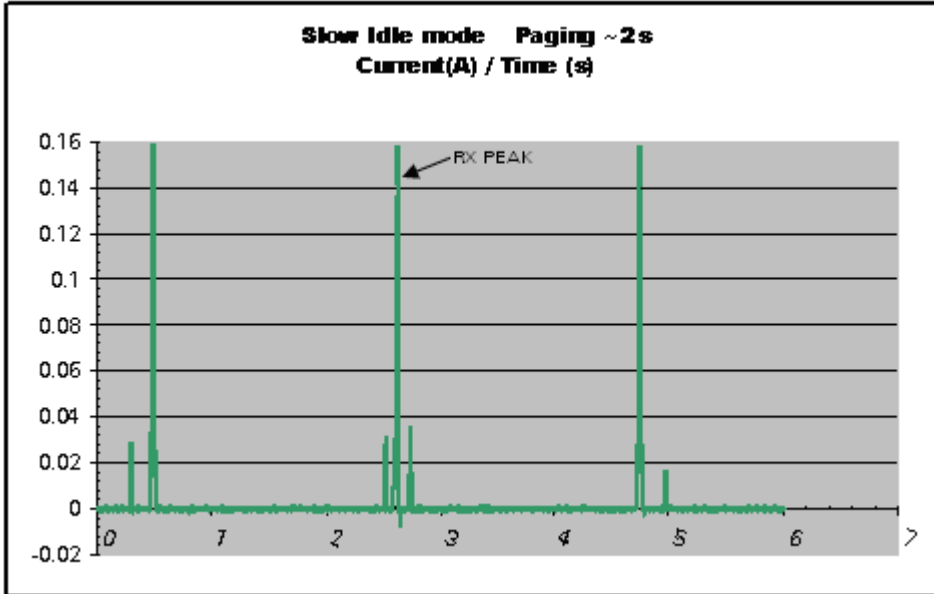
- Connected Mode (PCL5: Tx power 33dBm)
- Slow Idle mode (Paging 9)
- Fast idle mode (Paging 9)
- Transfer mode (GPRS class 10, gam.3: Tx power 33dBm)

The following waveform shows only the current curves.

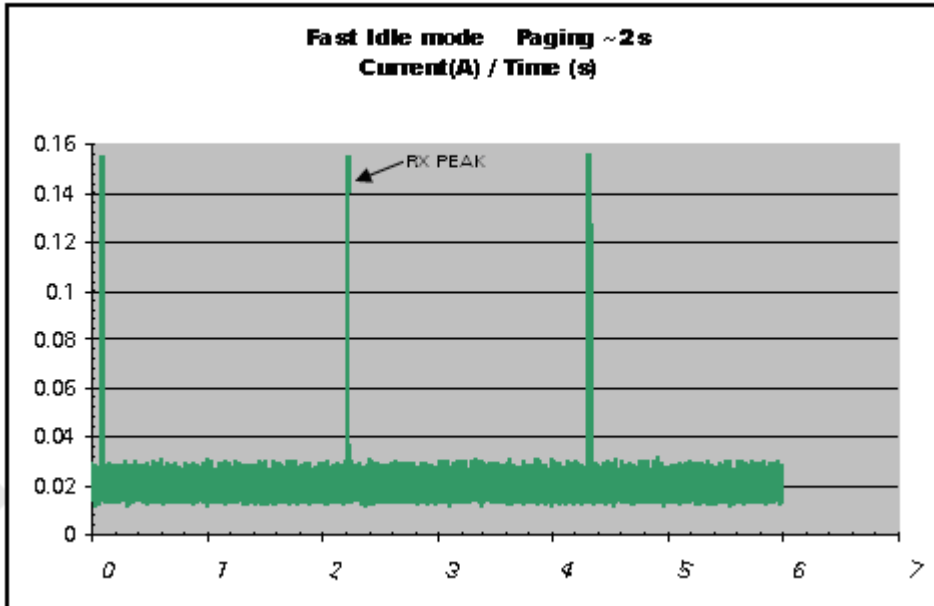
3.3.3.1 Connected Mode Current Waveform



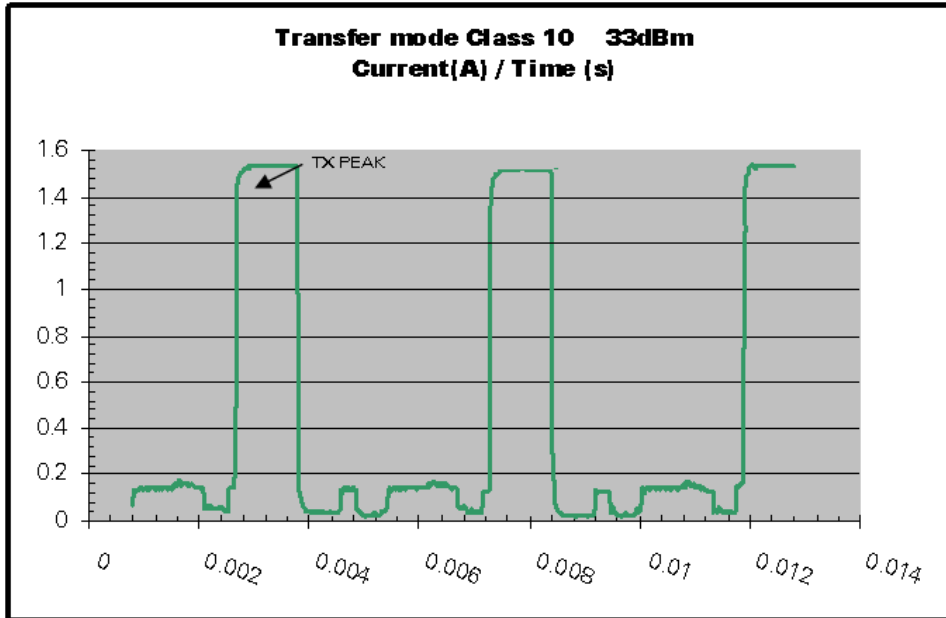
3.3.3.2 Slow Idle Mode Current Waveform



3.3.3.3 Fast Idle Mode Current Waveform



3.3.3.4 Transfer Mode Class 10 Current Waveform



3.3.4 Recommendations for Less Consumption

It is recommended to drive the GPIOs as indicated in the table below, especially when using the quiescent current.

Signal	Pin number	I/O	I/O type	Reset state	SW driver recommended (output state)
GPIO1	21	I/O	2V8-1	Z	0 logic level
GPIO2	22	I/O	2V8-1	Undefined	0 logic level
GPIO3	23	I/O	2V8-1	Undefined	0 logic level
GPIO4	24	I/O	2V8-1	Z	0 logic level
GPIO5	13	I/O	2V8-1	Z	0 logic level
GPIO6	33	I/O	2V8-1	Z	0 logic level
GPIO13	29	I/O	Pull-up	Pull-up*	0 logic level
GPIO14	30	I/O	Pull-up	Pull-up*	0 logic level
GPIO15	20	I/O	2V8-1	Z	0 logic level
GPIO16	35	I/O	2V8-1	Z	0 logic level

*GPIO13 and GPIO14 pull up are about 10K Ω.

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See chapter 3.4, "Electrical Information for Digital I/O" on page 30 for 2V8-1, 2V8-2, pull-up and open drain voltage characteristics and for Reset state definition.

If the LED is not necessary, it is possible to disable it.

For further details, refer to document [4] AT Command Interface Guide for Open AT[®] Firmware v6.5.

3.4 Electrical Information for Digital I/O

There are three types of digital I/O on the Q64: 2.8 volt CMOS type 1 (2V8-1), 2.8 volt CMOS type 2 (2V8-2) and Open drain.

The I/O concerned is all interfaces like GPIOs, PCM, etc.

The three types are described below:

Electrical characteristics of digital I/O

2.8 Volts type 1 (2V8-1)						
Parameter	I/O type	Minim.	Typ	Maxim.	Condition	
Internal 2.8V power supply	VCC_2V8	2.74V	2.8V	2.86V		
Input / Output pin	V _{IL}	CMOS	-0.5V*		0.84V	
	V _{IH}	CMOS	1.96V		3.2V*	
	V _{OL}	CMOS			0.4V	I _{OL} = - 4 mA
	V _{OH}	CMOS	2.4V			I _{OH} = 4 mA
	I _{OH}				4mA	
	I _{OL}				- 4mA	

*Absolute maximum ratings

2.8 Volts type 2 (2V8-2)						
Parameter	I/O type	Minim.	Typ	Maxim.	Condition	
Input / Output pin	V _{IL}	CMOS	-0.3V*		0.15V	
	V _{IH}	CMOS	1.6V		3.1V*	
	V _{OL}	CMOS			0.4V	I _{OL} = - 4 mA
	V _{OH}	CMOS	1.87V			I _{OH} = 4 mA
	I _{OH}				4mA	
	I _{OL}				- 4mA	

*Absolute maximum ratings

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Open drain outputs type						
Signal name	Parameter	I/O type	Minimum	Typ	Maximum	Condition
BUZZER	V_{OL}	Open Drain			0.4V	
	I_{OL}	Open Drain			100mA	

Pull-up outputs type						
Signal name	Parameter	I/O type	Minimum	Typ	Maximum	Condition
SDA / GPIO13 and SCL / GPIO14	V_{IH}	Pull-up	2V			
	V_{IL}	Pull-up			0.8V	
	V_{OL}	Pull-up			0.4V	
	I_{OL}	Pull-up			3mA	

SDA and SCL are internally pulled up with each 1 k Ω resistor to voltage 2.8V (VREF) inside the Q64 Wireless CPU[®].

The reset states for each I/O are given in the corresponding interface chapter descriptions. The state definitions are defined below:

Reset state definition	
Parameter	Definition
0	Set to GND
1	Set to supply 2V8
Pull down	Internal pull down with ~60K resistor.
Pull up	Internal pull up with ~60K resistor to supply 2V8.
Z	High impedance
Undefined	Be careful, undefined should not be used in your application if a special state is needed at reset. Those pins can be toggling signals during reset.

3.5 I2C Bus

3.5.1 Features

The I2C interface includes a clock signal (SCL) and a data signal (SDA) complying with a 100Kbit/s-standard interface (standard mode: s-mode).

3.5.1.1 Characteristics

The I²C bus is always master.

The maximum speed transfer range is 400Kbit/s (Fast mode: f-mode).

For more information on the bus, see document [7] "I²C Bus Specification", Version 2.0, Philips Semiconductor 1998.

3.5.1.2 I²C Waveforms

I²C bus waveform in master mode configuration:

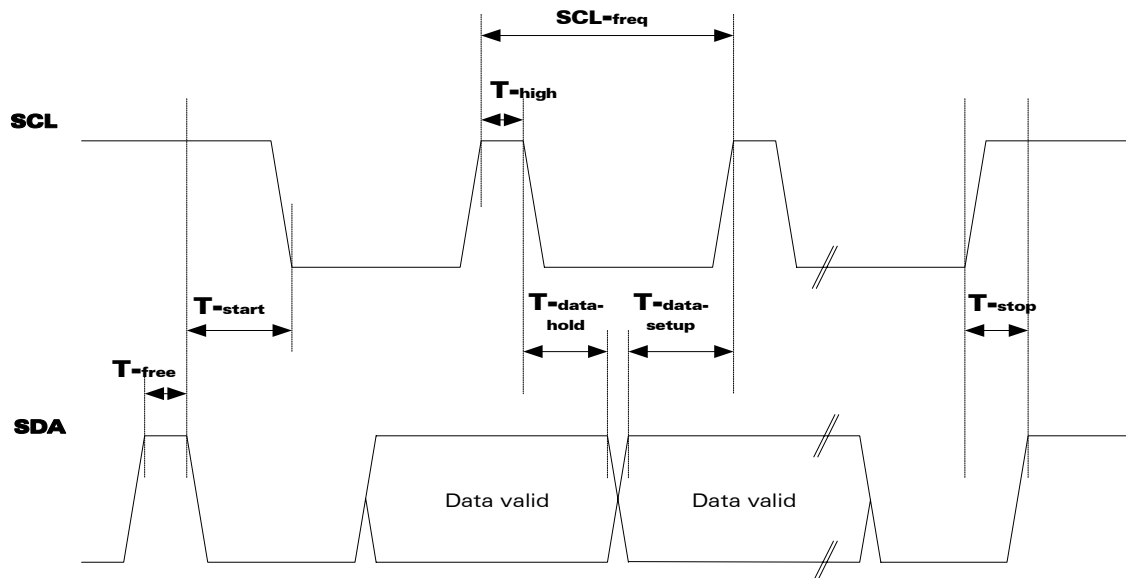


Figure 3: I²C Timing diagrams, Master

AC characteristics

Signal	Description	Minimum	Typ	Maximum	Unit
SCL-freq	I ² C clock frequency	100		400	KHz
T-start	Hold time START condition	0.6			μs
T-stop	Setup time STOP condition	0.6			μs
T-free	Bus free time, STOP to START	1.3			μs
T-high	High period for clock	0.6			μs
T-data-hold	Data hold time	0		0.9	μs
T-data-setup	Data setup time	100			ns

3.5.2 Pin Description

Signal	Pin number	I/O	I/O type	Reset state	Description	Multiplexed with
SDA	29	I/O	Pull-up	Pull-up*	Serial Data	GPIO13
SCL	30	O	Pull-up	Pull-up*	Serial Clock	GPIO14

*SDA and SCL pull-up are about 10K Ω

See chapter 3.4, "Electrical Information for Digital I/O" on page 30 for 2V8-1, 2V8-2, pull-up and open drain voltage characteristics and for Reset state definition.

The two lines are internally pulled up with each 1 KΩ resistor to voltage 2.8V (VREF) inside the Q64 Wireless CPU®.

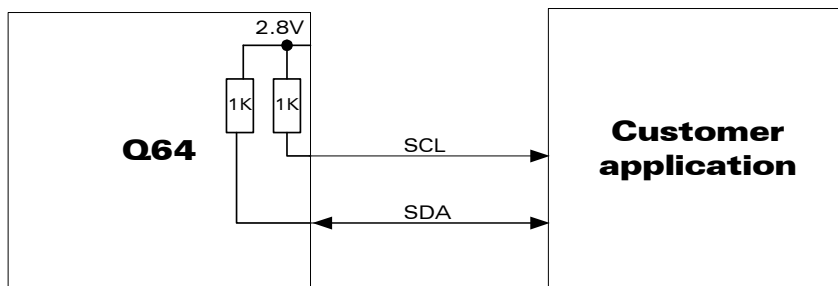


Figure 4: I²C bus configuration inside the Wireless CPU®

The I²C bus is compliant with the Standard mode (baud rate 100Kbit/s) and the Fast mode (baud rate 400Kbit/s).

3.6 Main Serial Link (UART1)

A flexible 8-wire serial interface is available, compliant with V24 protocol signaling, but not with V28 (electrical interface) due to a 2.8 volts interface.

3.6.1 Features

The maximum baud rate of the UART1 is 921 Kbit/s.

The signals are as follows:

- TX data (DTM1)
- RX data (DFM1)
- Request To Send (RTS1)
- Clear To Send (CTS1)
- Data Terminal Ready (DTR1)
- Data Set Ready (DSR1)
- Data Carrier Detect (DCD1)
- Ring Indicator (RI).

3.6.2 Pin Description

Signal	Pin number	I/O	I/O type	Reset state	Description	Multiplexed with
DTM1*	41	I	2V8-1	Z	Transmit serial data	GPIO18
DFM1*	42	O	2V8-1	1	Receive serial data	GPIO17
RTS1*	39	I	2V8-1	Z	Request To Send	GPIO9
CTS1*	40	O	2V8-1	Z	Clear To Send	GPIO12
DSR1*	32	O	2V8-1	Z	Data Set Ready	GPIO7
DTR1*	37	I	2V8-1	Z	Data Terminal Ready	GPIO10
DCD1*	38	O	2V8-1	Undefined	Data Carrier Detect	GPIO11
RI*	36	O	2V8-1	Undefined	Ring Indicator	GPIO8
GND	2, 4, 6, 8, 10, 12		GND		Ground	

See chapter 3.4, "Electrical Information for Digital I/O" on page 30 for 2V8-1, 2V8-2, pull-up and open drain voltage characteristics and for Reset state definition.

*According to PC view

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With the Open AT[®] Software Suite 1.0 / V2.0 when the UART1 service is run the multiplexed signals are unavailable for other purposes. Likewise, if one or more GPIOs (of this table) are allocated the UART1 service is unavailable.

The **rising time** and **falling time** of the reception signals (mainly DTM1) must be shorter than **300 ns**.

Recommendation:

The Q64 is designed to operate with all serial interface signals. It is mandatory to use RTS1 and CTS1 for hardware flow control in order to avoid data corruption during transmission.

5-wire serial interface hardware design:

- Signal: DTM1*, DFM1*, RTS1*, CTS1*
- The signal DTR1* must be managed following the V24 protocol signalling if we want to use the slow idle mode
- Please refer to the document [4] AT Command Interface Guide for Open AT[®] Firmware v6.5 for more information.

4-wire serial interface hardware design:

- DTM1*, DFM1*, RTS1*, CTS1*
- The signal DTR1* must be configured at the low level.
- Please refer to the document [4] AT Command Interface Guide for Open AT[®] Firmware v6.5 for more information.

2-wire serial interface hardware design:

- It is possible for connected external chip but not recommended (and forbidden for AT command or modem use)
- The flow control mechanism must be managed by the customer.
- DTM1*, DFM1*
- The signal DTR1* must be configured at the low level.
- The signals RTS1*, CTS1* are not used, please configure the AT command (AT+IFC=0,0 see document [4] AT Command Interface Guide for Open AT[®] Firmware v6.5).
- The signal RTS1* must be configured at the low level.
- Please refer to the document [4] AT Command Interface Guide for Open AT[®] Firmware v6.5 for more information.

3.6.3 Application

The level shifter must be set at 2.8V compliant with a V28 electrical signal.

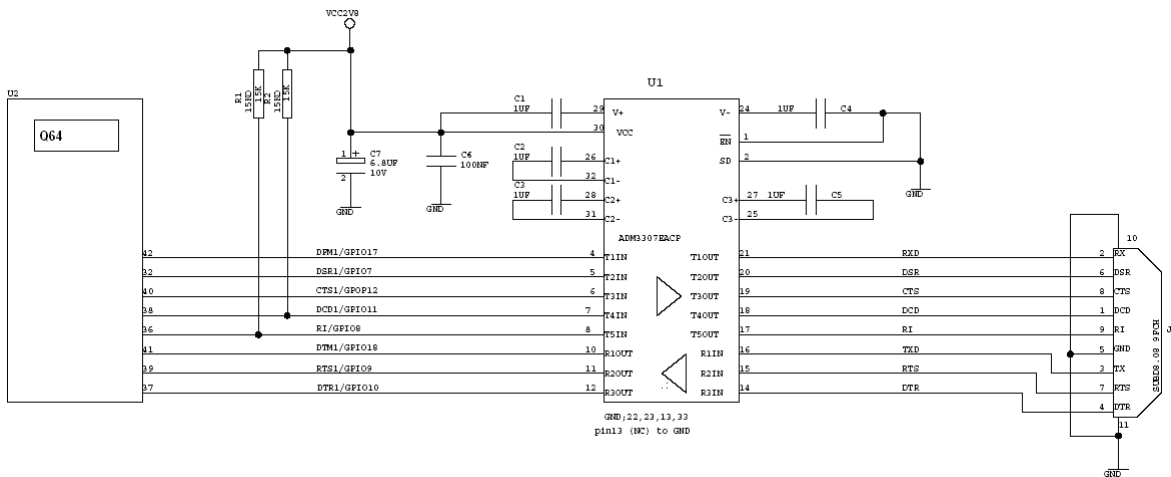


Figure 5: Example of RS-232 level shifter implementation for UART1

U1 chip also protects the Q64 against ESD at 15KV. (Air Discharge).

Recommended components:

- R1, R2 : 15KΩ
- C1, C2, C3, C4, C5 : 1uF
- C6 : 100nF
- C7 : 6.8uF TANTAL 10V CP32136 AVX
- U1 : ADM3307EACP ANALOG DEVICES
- J1 : SUB-D9 female

R1 and R2 are necessary only during Reset state to lift RI and DCD1 signals to high level.

The ADM3307EACP chip is able to reach **921Kb/s***. If other level shifters are used, make sure that their speeds are compliant with the UART1 speed.

*: For this baud rate, the power supply must be provided by an **external regulator at 3.0 V**.

The ADM3307EACP can be powered by an external regulator at 2.8 V (the baud rate will be limited up to 720kbps).

If the UART1 interface is connected directly to a host processor, it is not necessary to use level shifters. The interface can be connected as shown below:

V24/CMOS possible design:

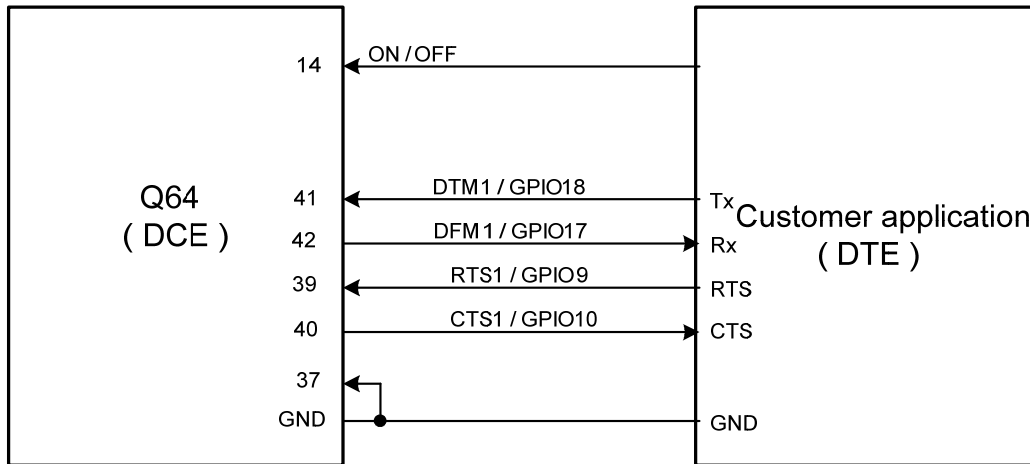


Figure 6: Example of V24/CMOS serial link implementation for UART1

The design shown in the figure above is a basic design.

However, a more flexible design to access this serial link with all modem signals is shown below:

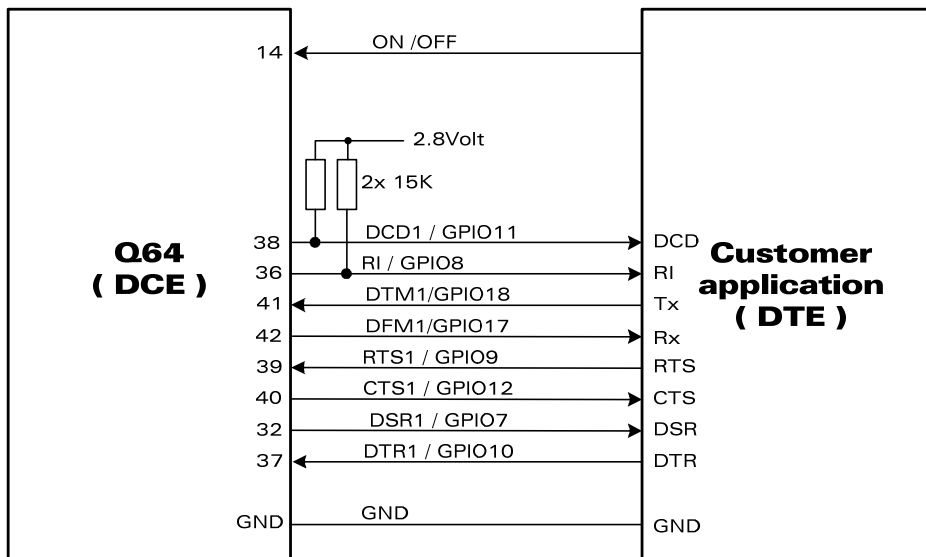


Figure 7: Example of full modem V24/CMOS serial link implementation for UART1

It is recommended to add a 15KΩ pull-up resistor on RI and DCD1 to set high level during reset state.

The UART1 interface is 2.8 volt type, but is 3 volt tolerant.

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The Q64 UART1 is designed to operate with all serial interface signals. It is mandatory to use RTS1 and CTS1 for hardware flow control in order to avoid data corruption during transmission.

Warning: If you want to activate Power down mode (Wavecom 32K mode) in your Open AT[®] application, you need to connect the DTR1 to a GPIO. Please refer to the document [4] AT Command Interface Guide for Open AT[®] Firmware v6.5 (see the "Appendixes") for more information on Wavecom 32K mode activation using the Open AT[®] Software Suite.

3.7 Auxiliary Serial Link (UART2)

An auxiliary serial interface (UART2) is available on Q64. This interface may be used to connect a Bluetooth or a GPS chip controlled by an Open AT® Plug-in.

3.7.1 Features

Maximum baud rate of the UART2 is 921 Kbit/s.

The signals are as follows:

- TX data (DTM3)
- RX data (DFM3)

2-wire serial interface hardware design:

- DTM3*, DFM3*
- Please configure the AT command (AT+IFC=0,0) to start accessing UART2.
- Please refer to the document [4] AT Command Interface Guide for Open AT® Firmware v6.5.

3.7.2 Pin Description

Signal	Pin number	I/O	I/O type	Reset state	Description
DTM3*	43	I	2V8-2	Z	Transmit serial data
DFM3*	44	O	2V8-2	Z	Receive serial data
GND*	2, 4, 6, 8, 10, 12		GND		Ground

* According to PC view

See chapter 3.4, "Electrical Information for Digital I/O" on page 30 for 2V8-1, 2V8-2, pull-up and open drain voltage characteristics and for Reset state definition.

3.7.3 Application

The voltage level shifter must be set at 2.8V and compliant with a V28 electrical signal.

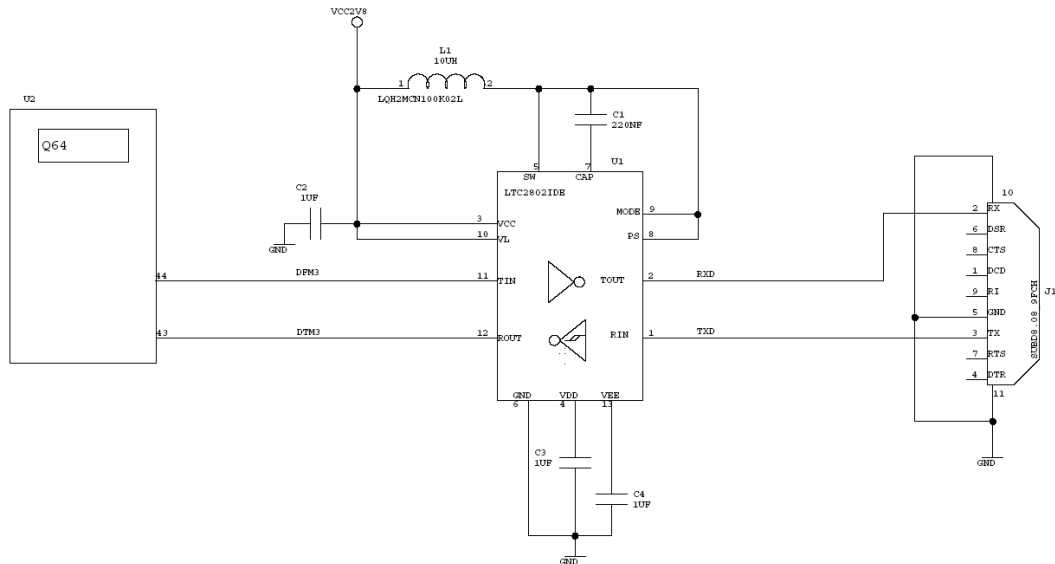


Figure 8: Example of RS-232 level shifter implementation for UART2

Recommended components:

Capacitors

- C1 : 220nF
- C2, C3, C4 : 1µF

Inductor

- L1 : 10µH

RS-232 Transceiver

- U1 : LINEAR TECHNOLOGY LTC2802IDE
- J1 : SUB-D9 female

The LTC2802 can be powered by an external regulator at 2.8 V.

The UART2 interface can be connected directly to others components if the voltage interface is 2.8 V.

3.8 SIM Interface

The Subscriber Identification Module can be directly connected to the Q64 through this dedicated interface.

3.8.1 Features

The SIM interface controls the 1.8V and 3V SIM cards.

It is recommended to add Transient Voltage Suppressor diodes (TVS) on the signal connected to the SIM socket in order to prevent any Electrostatic Discharge.

TVS diodes with low capacitance (less than 10 pF) must be connected on SIMCLK and SIMDAT signals to avoid any disturbance during the rising and falling edges.

These types of diodes are mandatory for the Full Type Approval. They shall be placed close to the SIM socket.

The following references can be used: **DALC208SC6** from ST Microelectronics.

5 signals exist:

- SIMVCC: SIM power supply.
- SIMRST: reset.
- SIMCLK: clock.
- SIMDAT: I/O port.
- SIMDET: SIM card detect.

The SIM interface controls a 3V / 1V8 SIM. This interface is fully compliant with GSM 11.11 recommendations concerning SIM functions.

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Electrical Characteristics of SIM interface

Parameter	Conditions	Minim.	Typ	Maxim.	Unit
SIMDAT V_{IH}	$I_{IH} = \pm 20\mu A$	$0.7 \times SIMVCC$			V
SIMDAT V_{IL}	$I_{IL} = 1mA$			0.4	V
SIMRST, SIMCLK V_{OH}	Source current = $20\mu A$	$0.9 \times SIMVCC$			V
SIMDAT V_{OH}	Source current = $20\mu A$	$0.8 \times SIMVCC$			
SIMRST, SIMDAT, SIMCLK V_{OL}	Sink current = $-200\mu A$			0.4	V
SIMVCC Output Voltage	SIMVCC = 2.9V $I_{VCC} = 1mA$	2.84	2.9	2.96	V
	SIMVCC = 1.8V $I_{VCC} = 1mA$	1.74	1.8	1.86	V
SIMVCC current	VCC = 3.6V			10	mA
SIMCLK Rise/Fall Time	Loaded with 30pF		20		ns
SIMRST, Rise/Fall Time	Loaded with 30pF		20		ns
SIMDAT Rise/Fall Time	Loaded with 30pF		0.7	1	μs
SIMCLK Frequency	Loaded with 30pF			3.25	MHz
SIMDET V_{IL}			0	0.5	V
SIMDET V_{IH}		1.5	1.8		V

Note:

When SIMDET is used, a **high to low** transition means that the SIM card is inserted and a **low to high** transition means that the SIM card is removed.

3.8.2 Pin Description

Signal	Pin number	I/O	I/O type	Reset state	Description	Multiplexed with
SIMCLK	19	O	2V9 / 1V8	0	SIM Clock	Not mux
SIMRST	17	O	2V9 / 1V8	0	SIM Reset	Not mux
SIMDAT	18	I/O	2V9 / 1V8	Pull up*	SIM Data	Not mux
SIMVCC	15	O	2V9 / 1V8	-	SIM Power Supply	Not mux
SIMDET	16	I	1V8	Pull-up#	SIM Card Detect	Not mux

*SIMDAT pull-up is about 10K Ω

#SIMDET pull-up is about 100 K Ω .

See chapter 3.4, "Electrical Information for Digital I/O" on page 30 for 2V8-1, 2V8-2, pull-up and open drain voltage characteristics and for Reset state definition.

3.8.3 Application

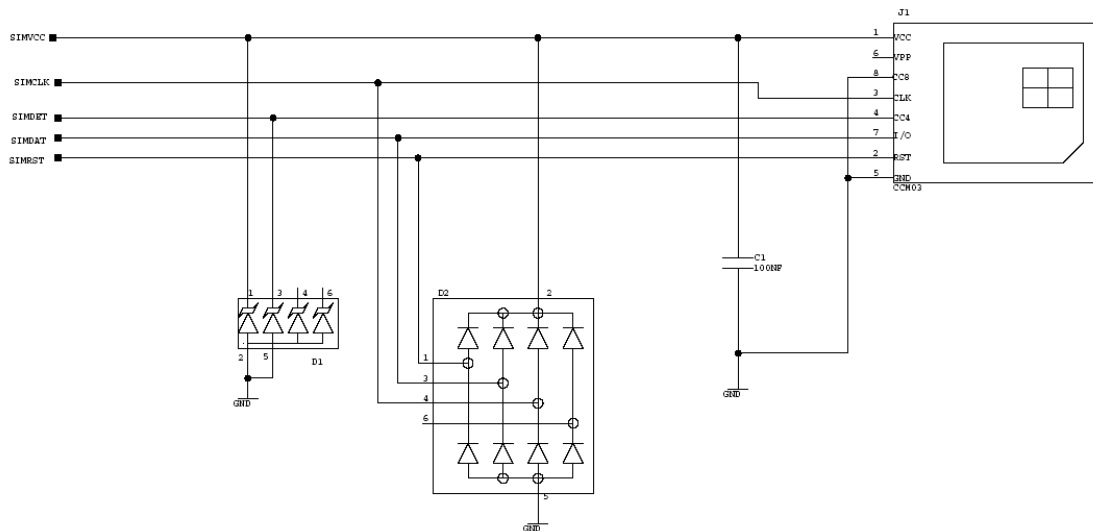


Figure 9: Example of SIM Socket implementation

Recommended components:

- C1 : 100nF
- D1 : ESDA6V1SC6 from ST
- D2 : DALC208SC6 from SGS-THOMSON
- J1 : ITT CANNON CCM03 series (See chapter 9.2 for more information)

The capacitor (C1) placed on the SIMVCC line must not exceed 330 nF.

SIM socket connection:

Pin description of the SIM socket

Signal	Pin number	Description
VCC	1	SIMVCC
RST	2	SIMRST
CLK	3	SIMCLK
CC4	4	SIMDET
GND	5	GROUND
VPP	6	Not connected
I/O	7	SIMDAT
CC8	8	GND

3.9 General Purpose Input/Output

The Wireless Microprocessor® provides up to 18 General Purpose I/O. They are used to control any external device such as a LCD, a Keyboard backlight.

3.9.1 Features

Reset State:

- 0 : Set to GND
- 1: Set to supply 2V8 depending.
- Pull down: Internal pull down with ~60K resistor.
- Pull up: Internal pull up with ~60K resistor to supply 1V8 or 2V8 depending on I/O type.
- Z: High impedance.
- Undefined: Be careful, undefined must not be used in your application if a special state at reset is needed. Those pins can be toggling signals.

3.9.2 Pin Description

Signal	Pin number	I/O	I/O type	Reset state	Multiplexed with
GPIO1	21	I/O	2V8-1	Z	NOT MUX
GPIO2	22	I/O	2V8-1	Undefined	NOT MUX
GPIO3	23	I/O	2V8-1	Undefined	NOT MUX
GPIO4	24	I/O	2V8-1	Z	NOT MUX
GPIO5	13	I/O	2V8-1	Z	ADIN4 / GPIO5
GPIO6	33	I/O	2V8-1	Z	LED
GPIO7	32	I/O	2V8-1	Z	DSR1
GPIO8	36	I/O	2V8-1	Pull up	RI
GPIO9	39	I/O	2V8-1	Z	RTS1
GPIO10	37	I/O	2V8-1	Z	DTR1
GPIO11	38	I/O	2V8-1	Undefined	DCD1
GPIO12	40	I/O	2V8-1	Z	CTS1
GPIO13	29	I/O	Pull-up	Pull up*	SDA
GPIO14	30	I/O	Pull-up	Pull up*	SCL
GPIO15	20	I/O	2V8-1	Z	NOT MUX

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Signal	Pin number	I/O	I/O type	Reset state	Multiplexed with
GPIO16	35	I/O	2V8-1	Z	NOT MUX
GPIO17	42	I/O	2V8-1	1	DFM1
GPIO18	41	I/O	2V8-1	Z	DTM1

*GPIO13 and GPIO14 pull-up are 1K Ω .

See chapter 3.4, "Electrical Information for Digital I/O" on page 30 for 2V8-1, 2V8-2, pull-up and open drain voltage characteristics and for Reset state definition.

3.10 Analog to Digital Converter

Three Analog to Digital Converters inputs are provided by the Q64. Those converters are 10 bits resolution, ranging from 0 to 2V.

3.10.1 Features

ADIN1/BAT-TEMP input can be used, typically, to monitor external temperature, useful for safety power off in case of application over heating (for Li-Ion battery). This input can also be used for customer application.

ADIN2, ADIN3 and ADIN4 input can be used for customer application

Electrical Characteristics of ADC

Parameter	Min	Typ	Max	Unit	Remark
Resolution		10		bits	
Sampling rate		216		S/s	
Input signal range	0		2	V	
Vref (DC Reference level)	1.15	1.20	1.25	V	
Integral Accuracy		15		mV	
Differential Accuracy		2.5		mV	
Input impedance to Vref.	ADIN1		1M	Ω	Multiplexed
	ADIN2		1M	Ω	
	ADIN3		1M	Ω	
	ADIN4		1M	Ω	

Note that ADIN3 and ADIN 4 are multiplexed. Only one of them is available at a time.

Depending if GR Plug-in is used, the AT commands to control ADC are different.

In Q64 with GR 64 plug-in, all ADIN inputs can be directly accessed through GR AT command, "AT+EADCREAD".

If without GR Plug-in, "AT+ADC" is used for accessing the ADIN1 and ADIN2 directly. For ADIN3 and ADIN4, they need to be selected which to be accessed by another AT command, "AT+WIOM", before accessing their ADC return values. The ADC sharing arrangement and the selection process are shown in Figure 10 and Figure 11 below:

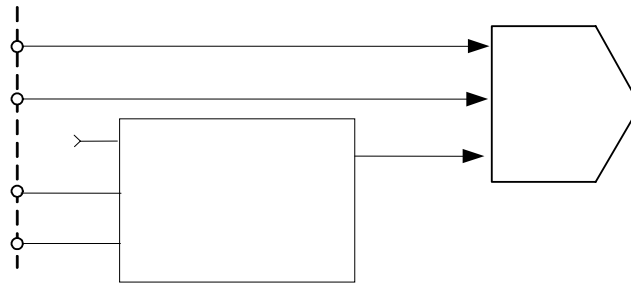


Figure 10: ADC sharing arrangement

GPIO29 inside WMP100 is used to control the selection between ADIN and ADIN4.

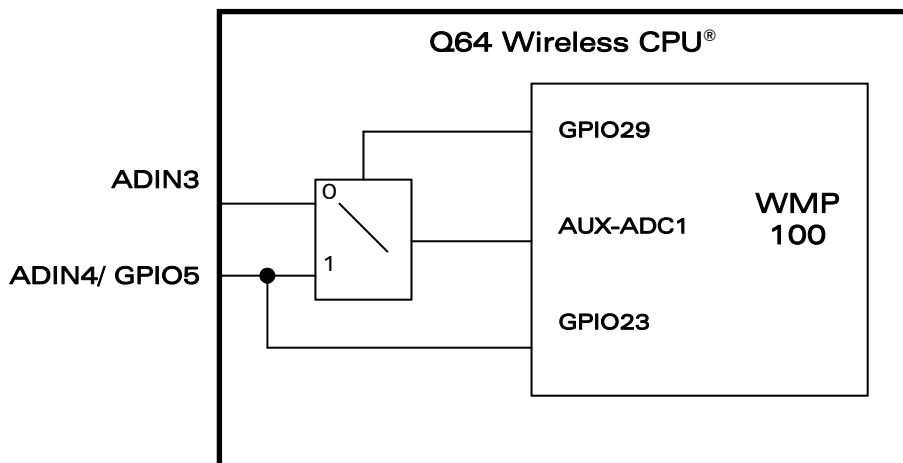


Figure 11: ADIN3 and ADIN4 sharing arrangement

To read ADIN3	To read ADIN4
Set GPIO29 as output Set GPIO29 as 0	Set GPIO29 as output Set GPIO29 as 1 GPIO23 must be released before
AT+WIOM=1,"GPIO29",1,0	AT+WIOM=1,"GPIO29",1,1 AT+WIOM=0,"GPIO23"

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Please refer to the following documents for the details of controlling the ADC access:

- [4] AT Command Interface Guide for Open AT[®] Firmware v6.5
- [9] [5] Q64 software user guide
- [6] AT Command Manual for GR64 and GS64 Wireless CPU[®]

3.10.2 Pin Description

Signal	Pin number	I/O	I/O type	Description
ADIN1*	26	I	Analog	A/D converter
ADIN2	27	I	Analog	A/D converter
ADIN3	28	I	Analog	A/D converter
ADIN4 / GPIO5	13	I or I/O	Analog or 2V8-1	A/D converter or GPIO5

*This input can be used for battery charging temperature sensor, see chapter "3.13 Battery Charging interface".

3.10.3 Application

The ADIN1/BAT-TEMP input is used for battery monitoring during charging of battery. All information is provided in the "Battery Charging" (see chapter 3.13).

3.11 Analogue Audio Interface

Two different microphone inputs and two different speaker outputs are supported. Audio 1 (MIC and EAR) is designed for handset type application and auxiliary audio is designed for car-kit type application.

The Q64 also includes an echo cancellation feature which allows hands-free function. In some cases, ESD protection must be added on the audio interface lines.

3.11.1 Microphone Features

Audio 1 can be configured in differential or single ended, while auxiliary audio can only be configured in single ended.

In audio 1, the connection can be either differential or single-ended but using a differential connection in order to reject common mode noise and TDMA noise is strongly recommended. Either in audio 1 or auxiliary audio, when using a single-ended connection, make sure to have a very good ground plane, a very good filtering as well as shielding in order to avoid any disturbance on the audio path. It is recommended to use the Q64 Wireless CPU® AREF pin for the good plane connection.

The gain of MIC inputs is internally adjusted and can be tuned using an AT command.

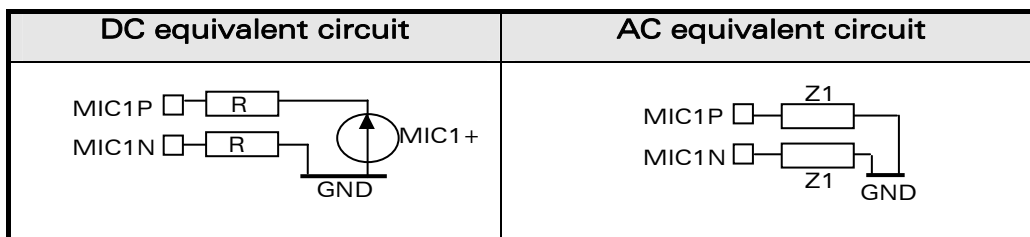
3.11.1.1 Electrical Characteristics

3.11.1.1.1 MIC1 Microphone Inputs

By default, the MIC1 inputs are differential ones, but they can be configured in single ended mode. They already include the convenient biasing for an electret microphone. The electret microphone can be directly connected on those inputs, thus allowing easy connection to a handset.

AC coupling is already embedded in the Wireless CPU®.

Equivalent circuits of MIC1



Electrical characteristics of MIC1

Parameters		Min	Typ	Max	Unit
Internal biasing DC Characteristics	MIC1+	2	2.1	2.2	V
	Output current		0.5	1.5	mA
	R2	1650	1900	2150	Ω
AC Characteristics 200 Hz<F<4 kHz	Z1 MIC1P (MIC1N=Open)	1.1	1.3	1.6	k Ω
	Z1 MIC1N (MIC1P=Open)				
	Z1 MIC1P (MIC1N=GND)	0.9	1.1	1.4	
	Z1 MIC1N (MIC1P=GND)				
	Impedance between MIC1P and MIC1N	1.3	1.6	2	
Maximum working voltage (MIC1P-MIC1N)	AT+VGT*=2		13.8		mVrms
	AT+VGT*=1		77.5		
	AT+VGT*=0		346		
Maximum rating voltage (MIC1P or MIC1N)	Positive			+7.35**	V
	Negative	-0.9			

- *The input voltage depends on the input microphone gain set by AT command. Please refer to the document [4] AT Command Interface Guide for Open AT® Firmware v6.5
- **Because MIC1P is internally biased, it is necessary to use a coupling capacitor to connect an audio signal provided by an active generator. Only a passive microphone can be directly connected to the MIC1P and MIC1N inputs.

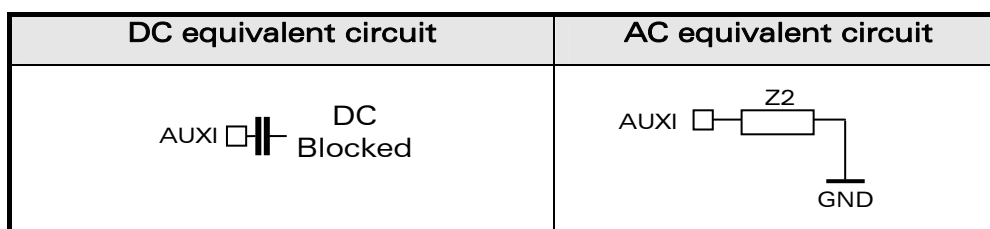
3.11.1.1.2 Auxiliary Microphone Inputs (AUXI)

The AUXI input is configured in single-ended.

The AUXI input does not include an internal bias. The AUXI input needs to have an external biasing if an electret microphone is used.

AC coupling is already embedded in the Q64 Wireless CPU®.

Equivalent circuits of AUXI



The AUXI input is a passive network applying -14dB gain followed by the transmit part of the CODEC.

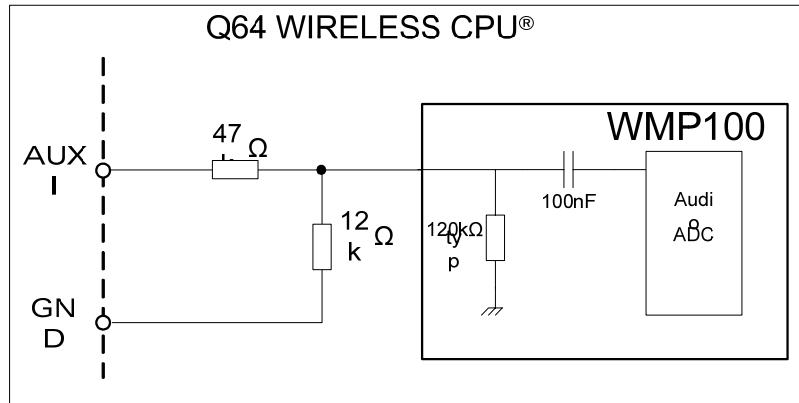


Figure 12: Auxiliary input connection to Q64 Wireless CPU®

Electrical Characteristics of AUXI

Parameters		Min	Typ	Max	Unit
DC Characteristics			0		V
AC Characteristics					
200 Hz < F < 4 kHz	Z2		60		KΩ
Maximum working voltage	AT+VGT*=2		40		mVrms
	AT+VGT*=1		190		
	AT+VGT*=0		850		
Maximum rating voltage	Positive			+12	V
	Negative	-2			V

- *The input voltage depends on the input microphone gain set by AT command. Please refer to the document [4] AT Command Interface Guide for Open AT® Firmware v6.5.

3.11.2 Speaker Features

The connection is single-ended on AUXO and is differential on EAR. Using a differential connection to reject common mode noise and TDMA noise is strongly recommended. Moreover in single-ended mode, 1/2 of the power is lost. When using a single-ended connection, make sure to have a very good ground plane, a very good filtering as well as shielding in order to avoid any disturbance on the audio path. It is recommended to use the Q64 Wireless CPU® AREF pin for good plane connection.

Parameter	Typ	Unit	Connection
Z (EARP, EARN)	4	Ω	single-ended mode
Z (EARP, EARN)	8	Ω	Differential mode
Z (AUXO)	16 or 32	Ω	single-ended mode

3.11.2.1 Speakers Outputs Power

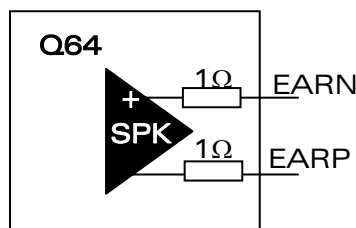
Both speakers maximum power output are not similar, due to the different configuration between the AUXO which is only single-ended and the EAR which can be differential, so EAR provides more power.

The maximal specifications given below are available with the maximum power output configuration values set by an AT command. The default values are recommended.

3.11.2.1.1 Speaker Outputs

The EAR interface allows differential and single-ended earpiece connection.

Equivalent circuits of SPK1



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Electrical characteristics of EAR

Parameters		Min	Typ	Max	Unit
Biasing voltage	EARP and EARN		1.30		V
Output swing voltage	RL=8Ω: AT+VGR=6*; single ended	-	-	2	Vpp
	RL=8Ω: AT+VGR=6*; differential	-	-	4	Vpp
	RL=32Ω: AT+VGR=6*; single ended	-	-	2.5	Vpp
	RL=32Ω: AT+VGR=6*; differential	-	-	5	Vpp
RL	Load resistance	6	8	-	Ω
IOUT	Output current; peak value; RL=8Ω	-	-	180	mA
POUT	RL=8Ω; AT+VGR=6*;	-	-	250	mW
RPD	Output pull-down resistance at power-down	28	40	52	KΩ
VPD	Output DC voltage at power-down	-	-	100	mV

*The output voltage depends on the output speaker gain set by AT command. Please refer to the document [4] AT Command Interface Guide for Open AT® Firmware v6.5.

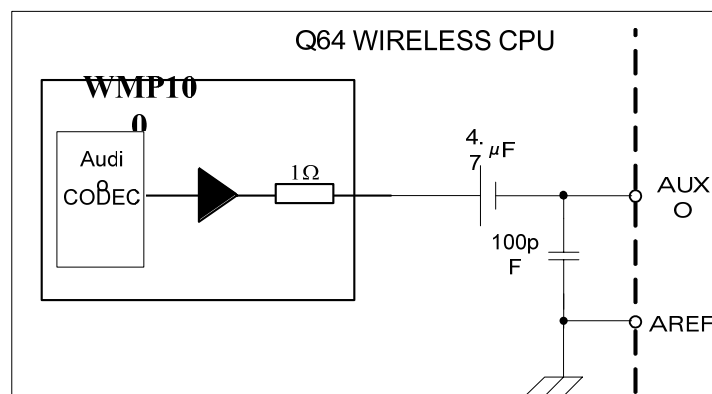
If a single-ended solution is used with the earpiece output, only one of the EAR must be chosen. The result is a maximal output power divided by 2.

3.11.2.1.2 Auxiliary Audio Output (AUXO)

With the AUXO interface, only single-ended speaker connection is allowed.

A filtering circuitry is already built inside the Q64.

Equivalent circuits of AUXO



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Electrical characteristics of AUXO

Parameters		Min	Typ	Max	Unit
Biasing voltage	Through coupling capacitor	-	-	-	V
Output swing voltage	RL=2kΩ; AT+VGR=6; single-ended	-	1.9	TBC	Vpp
RL	Load resistance	2	-	-	KΩ

*The output voltage depends on the output speaker gain set by AT command. Please refer to the document [4] AT Command Interface Guide for Open AT® Firmware v6.5.

3.11.3 Pin Description

Signal	Pin number	I/O	I/O type	Description
MIC1P	53	I	Analog	Microphone 1 positive input
MIC1N	54	I	Analog	Microphone 1 negative input
AUXI	57	I	Analog	Auxiliary audio input
EARP	55	O	Analog	Earpiece 1 positive output
EARN	56	O	Analog	Earpiece 1 negative output
AUXO	59	O	Analog	Auxiliary audio output
AREF	60	I	Ground	Analog Ground

3.11.4 Application

3.11.4.1 Microphone

3.11.4.1.1 MIC1 Differential Connection Example

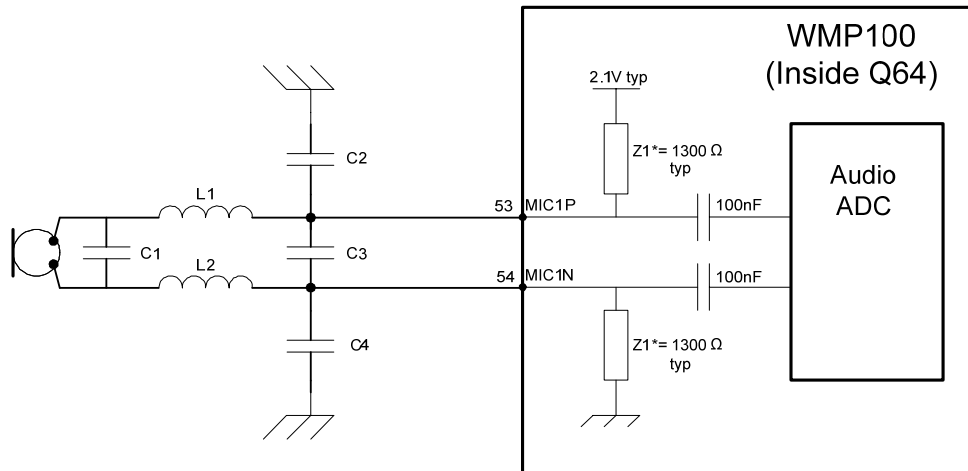


Figure 13: Example of MIC1 input differential connection with LC filter

*:Z1 is from 200Hz to 4kHz. For more characteristics refer to chapter 3.11.1.1.1.

Note: Audio quality can be very good without L1, L2, C2, C3, and C4 depending on the design. But if there is EMI perturbation, this filter can reduce the TDMA noise. This filter (L1, L2, C2, C3, C4) is not mandatory. If not used, the capacitor must be removed and coil replaced by 0 Ω resistors as shown in the following schematic.

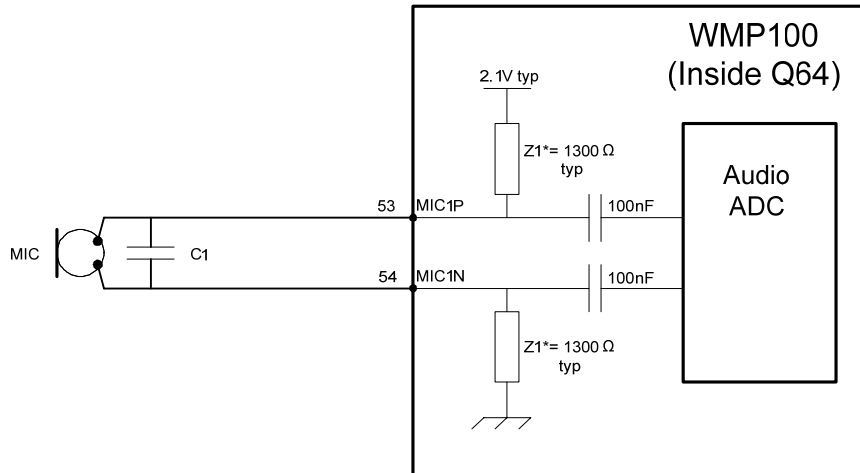


Figure 14: Example of MIC1 input differential connection without LC filter

*:Z1 is from 200Hz to 4kHz. For more characteristics refer to the chapter 3.11.1.1.1.

The capacitor C1 is highly recommended to eliminate the TDMA noise. C1 must be close to the microphone.

Recommended components:

- C1 : 12pF to 33pF (needs to be tuned depending on the design)
- C2, C3, C4 : 47pF (need to be tuned depending on the design)
- L1, L2 : 100nH (need to be tuned depending on the design)

3.11.4.1.2 MIC1 Single-ended Connection Example

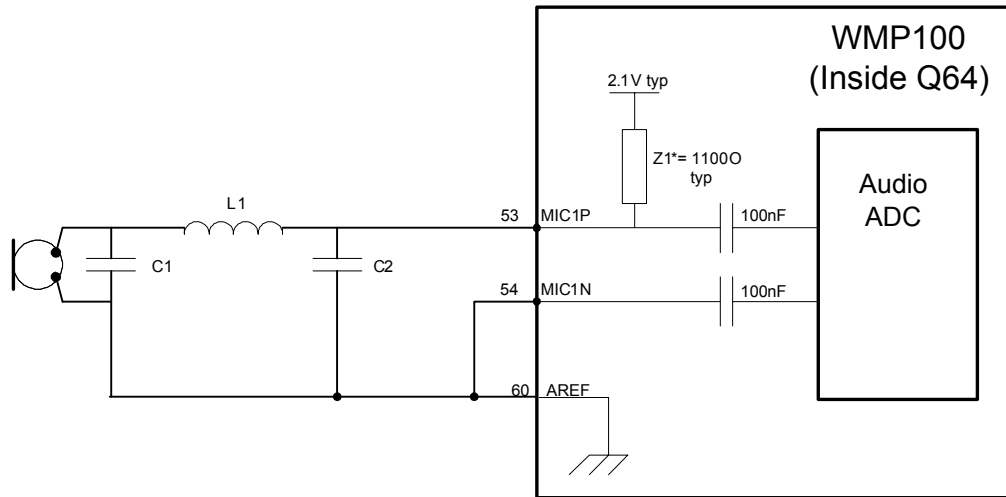


Figure 15: Example of MIC1 input single-ended connection with LC filter

*:Z1 is from 200Hz to 4kHz. For more characteristics refer to chapter 3.11.1.1.1.

Internal input impedance value becomes 1100 Ω, due to the connection of MIC1N to ground.

It is recommended to use the Q64 Wireless CPU® AREF pin for good ground connection.

It is recommended to add L1 and C2 footprint to add a LC filter to reduce the TDMA noise.

When not used, the filter can be removed by replacing L1 by a 0 Ω resistor and by disconnecting C2, as the following schematic.

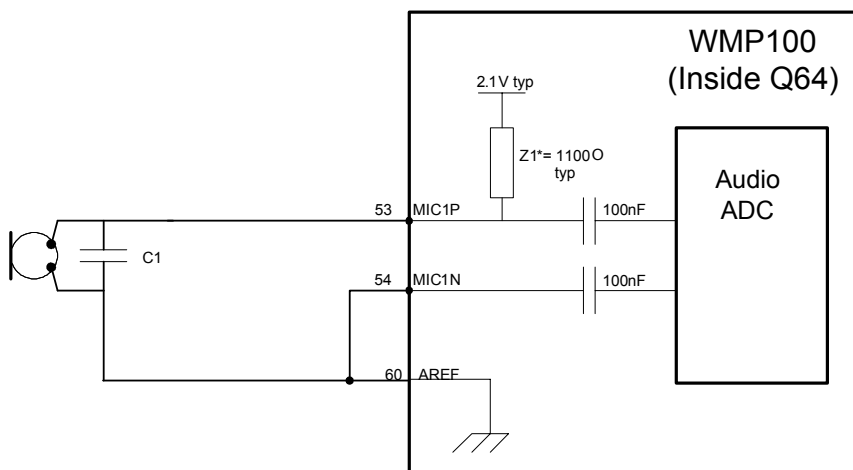


Figure 16: Example of MIC1 input single-ended connection without LC filter

*:Z1 is from 200Hz to 4kHz. For more characteristics refer to the chapter 3.11.1.1.1.

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The capacitor C1 is highly recommended to eliminate the TDMA noise. C1 must be close to the microphone.

Recommended components:

- C1: 12pF to 33pF (needs to be tuned depending on the design)
- C2: Need to be tuned depending on the design.
- L1: Need to be tuned depending on the design.

3.11.4.1.3 AUXI connection example

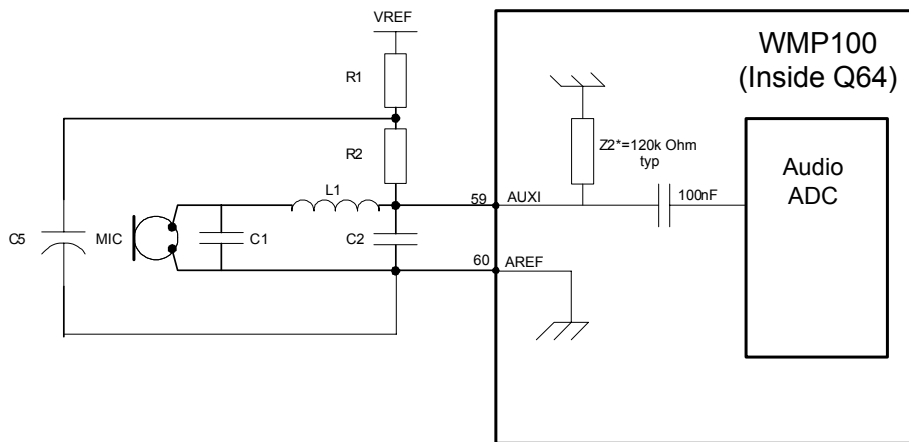


Figure 17: Example of AUXI input single-ended connection with LC filter

*:Z2 is from 200Hz to 4kHz. For more characteristics refer to chapter 3.11.1.1.2.

While using a single-ended connection in AUXI, ensure to have a good ground plane, a good filtering and shielding, in order to avoid any disturbance on the audio path. It is recommended to use the Q64 Wireless CPU® AREF pin for good plane connection.

It is recommended to add L1 and C2 footprint to add a LC EMI filter to try to eliminate the TDMA noise.

When not used, the filter can be removed by replacing L1 by a 0 Ω resistor and by disconnecting C2, as shown in the following schematic.

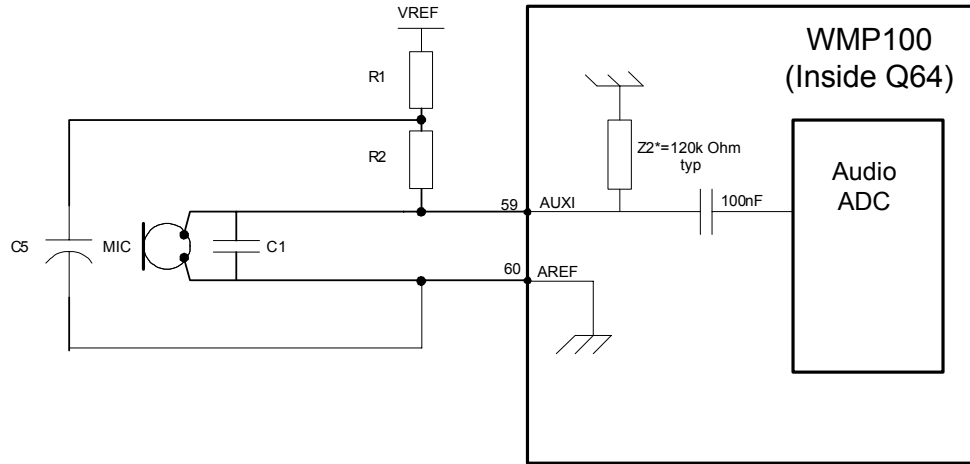


Figure 18: Example of AUXI input single-ended connection without LC filter

*:Z2 is from 200Hz to 4kHz. For more characteristics refer to the chapter 3.11.1.1.2.

Recommended components:

- R1: 4K7 Ω (for the bias voltage equal to 2.8V)
- R2: 820 Ω
- C1: 12pF to 33pF (needs to be tuned depending on the design)
- C2: Need to be tuned depending on the design.
- C5 : 2.2uF +/- 10%
- L1: Need to be tuned depending on the design.

Since AUXI is very sensitive to audio noise, it is strongly recommended to use VREF (pin 34) for voltage biasing or to ensure to use a “clean” source.

CAUTION: If VREF is not used TDMA noise can degrade quality.

The capacitor C1 is highly recommended to reduce the TDMA noise. C1 must be close to the microphone.

3.11.4.2 Speaker

3.11.4.2.1 EAR Differential Connection

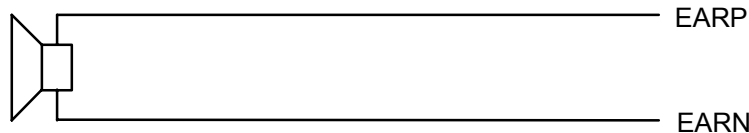


Figure 19: Example of Speaker differential connection

Impedance of the speaker amplifier output in differential mode is:

$$R \leq 2\Omega \text{ +/- } 10\%$$

The connection between the Q64 pins and the speaker/earpiece must be designed to keep the serial impedance lower than 3Ω in the differential mode.

3.11.4.2.2 EAR Single-ended Connection

Typical implementation:

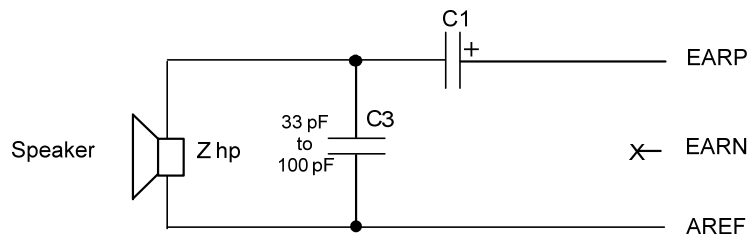


Figure 20: Example of Earpiece/Speaker single-ended connection

$4.7\mu\text{F} < C1 < 47\mu\text{F}$ (depending on speaker characteristics and output power).

A decoupling capacitor C3 is highly recommended to eliminate the TDMA noise. C3 must be close to the speaker.

Using a single-ended connection includes losing of the output power (- 6 dB) compared to a differential connection.

The connection between the Q64 pins and the speaker must be designed to keep the serial impedance lower than 1.5Ω in the single-ended mode.

While using a single-ended connection in EAR, ensure to have a good ground plane, a good filtering and shielding, in order to avoid any disturbance on the audio path. It is recommended to use the Q64 Wireless CPU® AREF pin for the good plane connection.

If EARP channel is used, EARN can be left open.

If EARN channel is used, EARP can be left open.

3.11.4.2.3 AUXO Connection

Typical implementation:

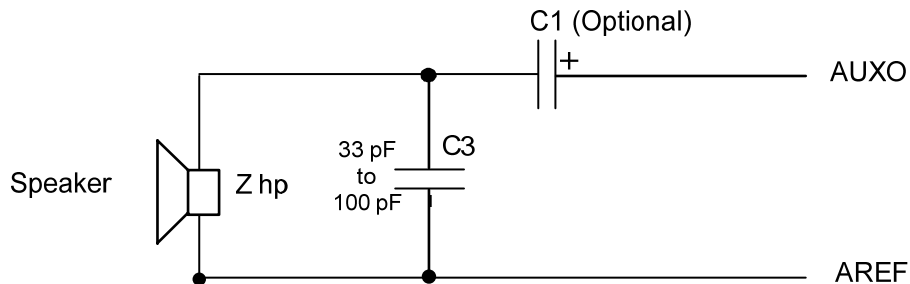


Figure 21: Example of AUXO connection

An capacitor C1 ($4.7 \mu\text{F} < C1 < 47 \mu\text{F}$) can be added (optional)(depending on speaker characteristics and output power).

A decoupling capacitor C3 is highly recommended to reduce the TDMA noise. C3 must be close to the speaker.

The connection between the Q64 pin and the speaker must be designed to keep the serial impedance lower than 1.5Ω in single-ended mode.

While using a single-ended connection in AUXO, ensure to have a good ground plane, a good filtering and shielding, in order to avoid any disturbance on the audio path. It is recommended to use the Q64 Wireless CPU® AREF pin for the good plane connection.

3.11.5 Design Recommendation

3.11.5.1 General

When speakers and microphones are used outside, it is recommended to add ESD protection as close as possible to the speaker or microphone, connected between the audio lines and a good ground.

The microphone connections may be either differential or single-ended in MIC1, but using a differential connection is strongly recommended to reject common mode noise and TDMA noise.

While using a single-ended connection in MIC1 or AUX1, ensure to have a good ground plane, a good filtering as well as shielding, in order to avoid any disturbance on the audio path. It is recommended to use the Q64 Wireless CPU® AREF pin for the good plane connection.

It is important to select the appropriate microphone, speaker and filtering components to avoid TDMA noise

3.11.5.2 Recommended Microphone Characteristics

The microphone impedance must be around 2 K Ω .

Sensitivity from -40dB to -50 dB.

SNR > 50 dB.

Frequency response compatible with the GSM specifications.

To reduce TDMA noise, it is highly recommended to use microphones with two internal decoupling capacitors:

- CM1=56pF (0402 package) for the TDMA noise generated by the demodulation of the GSM 850 and GSM900 frequency signal.
- CM2=15pF (0402 package) for the TDMA noise generated by the demodulation of the DCS/PCS frequency signal.

The capacitors must be soldered in parallel to the microphone.

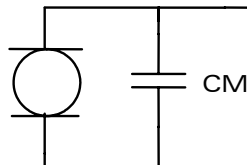


Figure 22: Microphone

3.11.5.3 Recommended Speaker Characteristics

Speakers: Electro-magnetic /10mW

Impedance: 8Ω for hands-free (EAR)

Impedance: 32Ω for heads kit (AUXO)

Sensitivity: 110dB SPL min

Receiver frequency response compatible with the GSM specifications.

3.11.5.4 Recommended Filtering Components

When designing a GSM application, it is important to select the right audio filtering components.

The strongest noise, called TDMA, is mainly due to the GSM850/GSM900/DCS1800 demodulation and PCS1900 signal: A burst being produced every 4.615ms; the frequency of the TDMA signal is equal to 216.7Hz plus harmonics.

The TDMA noise can be suppressed by filtering the RF signal by using the right decoupling components.

The types of filtering components are:

- RF decoupling inductors
- RF decoupling capacitors

A good "Chip S-Parameter" simulator is proposed by Murata, please visit the website to find more information:

<http://www.murata.com/designlib/mcsil.html>

When using different Murata components, the value, the package and the current rating can have different decoupling effects.

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The table below shows some examples with different Murata components:

Package	0402		
Filtered band	GSM900	GSM 850/900	DCS/PCS
Value	100nH	56pF	15pF
Types	Inductor	Capacitor	Capacitor
Position	Serial	Shunt	Shunt
Manufacturer	Murata	Murata	Murata
Rated	150mA	50V	50V
Reference	LQG15HSR10J02 or LQG15HNR10J02	GRM1555C1H560JZ01	GRM1555C1H150JZ01 or GRM1555C1H150JB01
Package	0603		
Filtered band	GSM900	GSM 850/900	DCS/PCS
Value	100nH	47pF	10pF
Types	Inductor	Capacitor	Capacitor
Position	Serial	Shunt	Shunt
Manufacturer	Murata	Murata	Murata
Rated	300mA	50V	50V
Reference	LQG18HNR10J00	GRM1885C1H470JA01 or GRM1885C1H470JB01	GRM1885C1H150JA01 or GQM1885C1H150JB01

3.11.5.5 Audio Track and PCB Layout Recommendation

To avoid TDMA noise, it is recommended to surround the audio tracks by ground:

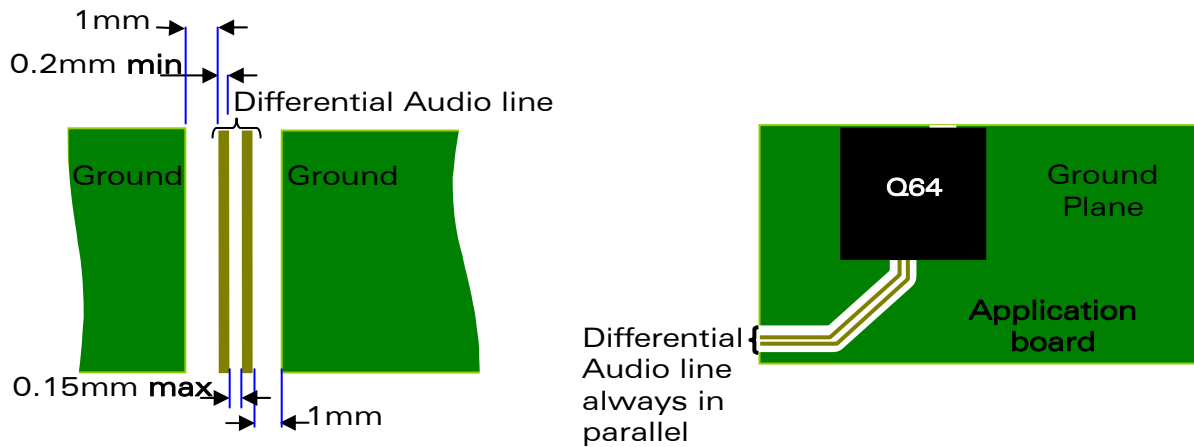


Figure 23: Audio track design

Remark:

Avoid digital tracks crossing under and over the audio tracks.

3.12 PWM / Buzzer Output

This output is controlled by a PWM controller and provides a buzzer service.

3.12.1 Features

The BUZZER is an open drain one. A buzzer can be directly connected between this output and VCC. The maximum current is 100 mA (PEAK).

Electrical characteristics

Parameter	Condition	Minimum	Maximum	Unit
V_{OL}	$I_{ol} = 100mA$		0.4	V
I_{PEAK}	$VCC = VCCmax$		100	mA
Frequency		3	10000*	Hz
Duty cycle		0*	100*	%

*Notes

Mind the maximum frequency and the minimum/maximum duty cycle; they are limited due to the RC configuration.

When the limits are approached, the amplitude modulation is less fine.

3.12.2 Pin Description

Signal	Pin number	I/O	I/O type	Reset state	Description
BUZZER	31	O	Open drain	Z	Buzzer output

See chapter 3.4, "Electrical Information for Digital I/O" on page 30 for 2V8-1, 2V8-2, pull-up and open drain voltage characteristics and for Reset state definition.

3.12.3 Application

The maximum peak current is 100 mA and the maximum average current is 40 mA. A diode against transient peak voltage must be added as described below.

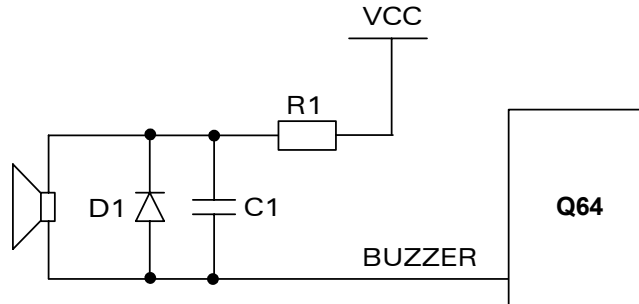


Figure 24: Example of buzzer implementation

Where:

R1 must be chosen in order to limit the current at I_{PEAK} max and must be adjusted in function of the frequency and the duty cycle used.

C1 = 0 to 100 nF (depending on the buzzer type)

D1 = BAS16 (for example)

A low filter is recommended at low frequencies.

Calculation of the Low Filter:

Req is the total resistor in line.

C is the capacitive charge on BUZZER signal and the ground

The cut-off frequency (F_c) must be higher than F_{BUZZER}

Due to the conception of the signal, the frequency modulation of the BUZZER signal is $64 * F_{BUZZER}$

$$F_c \text{ must be at least } 64 * F_{BUZZER}.$$

$$F_c = 1 / (2.\pi.Req.C)$$

Recommended characteristics for the buzzer:

- Electro-magnetic
- Impedance: 7 to 30 Ω
- Sensitivity: 90 dB SPL min @ 10 cm
- Current: 60 to 90 mA

The BUZZER output can also be used to drive a LED as shown in the Figure below:

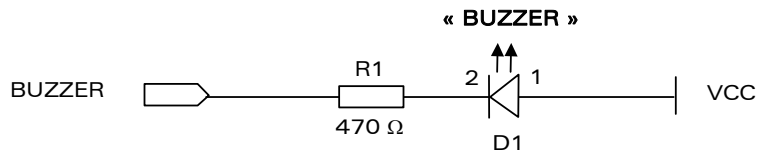


Figure 25: Example of LED driven by the BUZZER output

R1 value can be set according to the LED (D1) characteristics.

3.13 Battery Charging Interface

The Q64 Wireless CPU® supports one battery charging circuit, two algorithms and one hardware charging mode (pre-charging) for 3 battery technologies:

- Ni-Cd (Nickel-Cadmium) with algorithm 0
- Ni-Mh (Nickel-Metal Hydride) with algorithm 0
- Li-Ion (Lithium-Ion) with algorithm 1

The two algorithms control a switch, which connects the CHG_IN signal to the VCC signal. The algorithms control the frequency and the connected time of the switching. During the charging procedure, battery charging level is controlled and when the Li-Ion algorithm is used, battery temperature is monitored via the ADIN1/BAT-TEMP ADC input.

One more charging procedure is provided by the Q64 Wireless CPU®, called “Pre-charging” mode, but it is a special charging mode as it is only activated when the Wireless CPU® is OFF. Control is thus only performed by the hardware. The purpose of this charging mode is to avoid battery damage; it prevents the battery from being below the minimum level.

3.13.1 Implementation

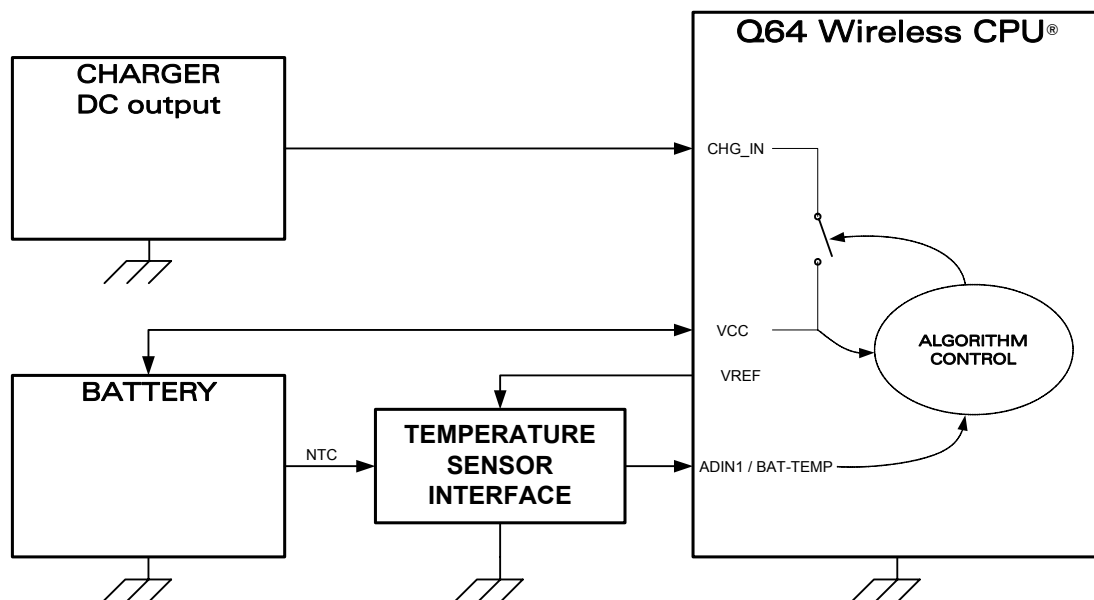


Figure 26: Charging block diagram

The Q64 charging circuit is composed of a transistor switch (between CHG_IN pin 11 and VCC pins 1, 3, 5, 7, 9). Charging is controlled by 2 software algorithms.

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A dedicated ADC input, ADIN1/ BAT-TEMP pin 26, for temperature monitoring (only for Li-Ion battery technologies).

To use the charging functionality, three items of hardware are required:

- A charger power supply

This provides a DC power supply limited to 800mA and with a voltage range according to the battery chosen and the Q64 specification.

- A battery

The charging functionality must be used with rechargeable batteries only. Three battery types are supported: Li-Ion, Ni-Mh and Ni-Cd.

If the Q64 Wireless CPU is not powered (VCC pin 1, 3, 5, 7, 9) by a rechargeable battery, the CHG_IN input (pin 11) must be left open.

- An analog temperature sensor

The analog temperature sensor is only used with Li-Ion batteries for battery temperature monitoring. This sensor is composed of an NTC sensor and several resistors.

3.13.2 Ni-Cd / Ni-Mh Charging Algorithm

To charge the battery, the algorithm measures battery level when the switch is open (T2) and charges the battery by closing the switch (T3). When the battery is charged (battery voltage has reached BattLevelMax) the switch is open for time T3.

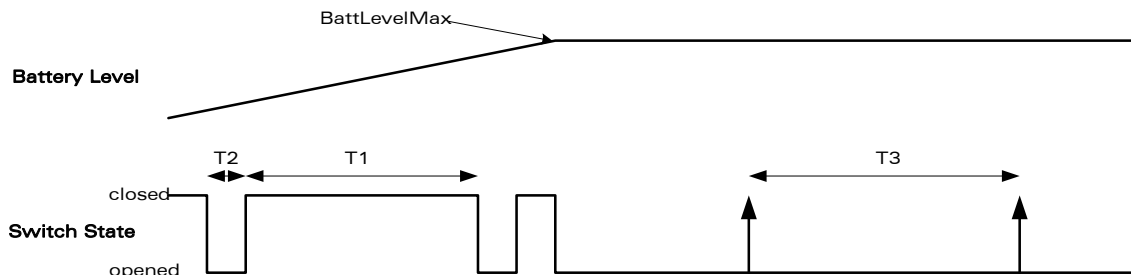


Figure 27: Ni-Cd / Ni-Mh charging waveform

Electrical characteristics of Ni-Cd / Ni-Mh battery timing charge

Parameter	Min	Typ	Max	Unit
T1		1		s
T2		0.1		s
T3		5		s

Note: T1, T2, T3 and BattLevelMax may be configured by AT command.

The battery level is monitored by the software (but not temperature).

3.13.3 Li-Ion Charging Algorithm

The Li-Ion algorithm provides battery temperature monitoring, which is highly recommended to prevent battery damage during the charging phase.

The Li-Ion charger algorithm can be divided in three phases:

1. Constant charge
2. Beginning of pulse charge
3. End of pulse charge

The three phases can be seen on the following waveform for full charging:

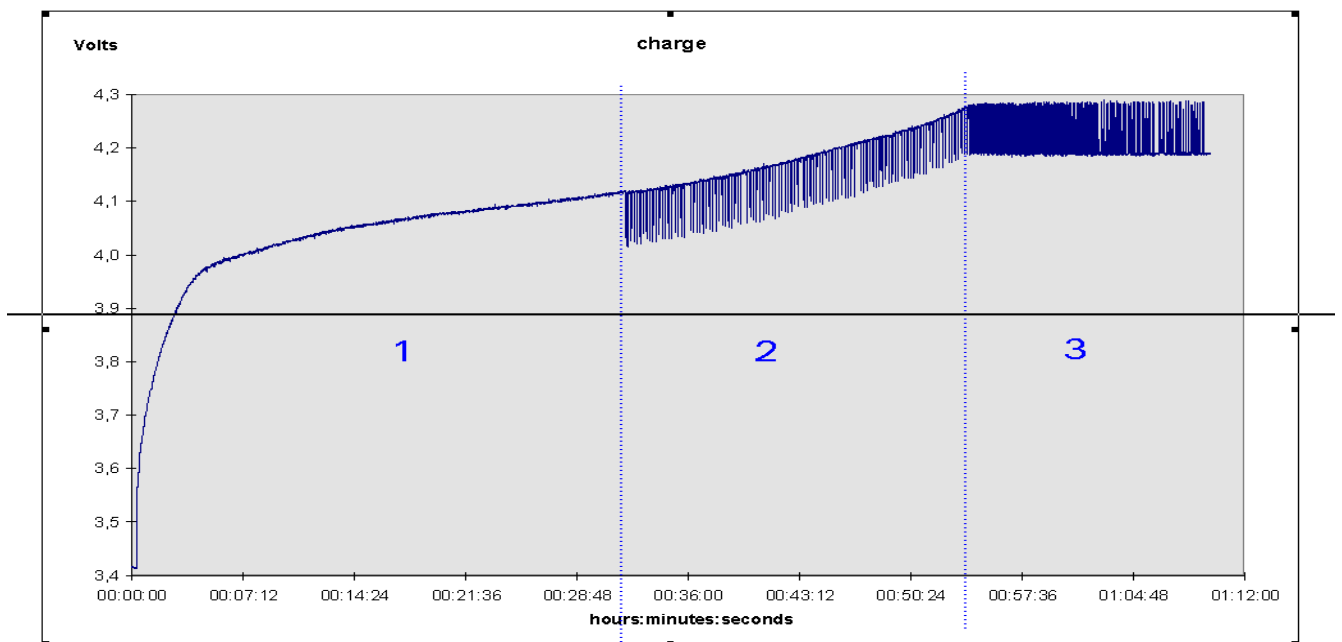


Figure 28: Li-Ion full-charging waveform

Electrical characteristics of Li-Ion battery timing charge

Parameter		Min	Typ	Max	Unit
Step 1 switching	Closed		Always		s
Step 2 switching	Opened		0.1		s
	Closed		1		s
Step 3 switching	Opened	0.1		3	s
	Closed		1		s

3.13.4 Controlled Pre-charging Hardware

There is another charging mode, Pre-charging mode, which is hardware-controlled and not software-controlled. This mode is only activated when the Wireless CPU® is OFF and when VCC is in the voltage range of $2.8V < VBATT < 3.2V$. The power supply charger must be connected to CHG_IN (pin 11). In Pre-charging mode, the battery is charged with a direct current of 50mA.

This mode is not a real charging mode as it is not possible to obtain a full charge with it, but it is useful to save battery life by preventing the battery from being below the low limit voltage value.

3.13.5 Temperature Monitoring

Temperature monitoring is only available for the Li-Ion battery with algorithm 1. The ADIN1/BAT-TEMP (pin 26) ADC input must be used to sample the temperature analog signal provided by an NTC temperature sensor. The minimum and maximum temperature range may be set by AT command.

Pin description of battery charging interface

Signal	Pin number	I/O	I/O type	Description
CHG_IN	11	I	Analog	Current source input
ADIN1/ BAT-TEMP	26	I	Analog	A/D converter

Electrical characteristics of battery charging interface

Parameter		Minimum	Typ	Maximum	Unit
Charging operating temperature		0		50	°C
ADIN1 / BAT-TEMP (pin 26)	Resolution		10		bits
	Sampling rate		216		S/s
	Input Impedance (R)		1M		Ω
	Input signal range	0		2	V
CHG_IN (pin 11)	Voltage (for I=Imax)	4.6*			V
	Voltage (for I=0)			6*	V
	Current Imax			800	mA

* To be configured as specified by the battery manufacturer

3.14 ON / OFF Signal

This input is used to switch ON or OFF the Wireless CPU®.

A low level signal must be provided on the pin ON/OFF to switch ON the Wireless CPU®. The voltage of this signal must be maintained at low level during a minimum of 1500ms. This signal can be left at high level until switched off.

To power OFF the Wireless CPU®, the steps depends on whether the Q64 has GR plug-in embedded.

- If the Wireless CPU® has GR plug-in, the pin ON/OFF must also be maintained at low level during a minimum of 500ms and then set it back to high level. The Wireless CPU® can be switched off through the GR plug-in and the Operating System.
- If there is no GR plug-in in the Wireless CPU®, the ON/OFF pin must be maintained at high level. The Wireless CPU® can be switched off through the Operating System.
- Please refer to section 3.14.3.2 for further information of Power-OFF sequence.

Warning:

All external signals must be inactive when the CPU® is OFF to avoid any damage when starting and allow Wireless CPU® to start and stop correctly.

3.14.1 Features

Electrical characteristics of the signal

Signal	Parameter	Minimum	Maximum	Unit
ON/OFF	V _{IL}		0.5	V
	V _{IH}	1.5	VCC	V

3.14.2 Pin Description

Signal	Pin number	I/O	Impedance	Description
ON/OFF	14	I	10 kΩ*	Q64 Power-ON

*Remark: The ON/OFF pin is connected to a PNP transistor before going into the Q64 baseband network and WMP100, shown in Figure 29.

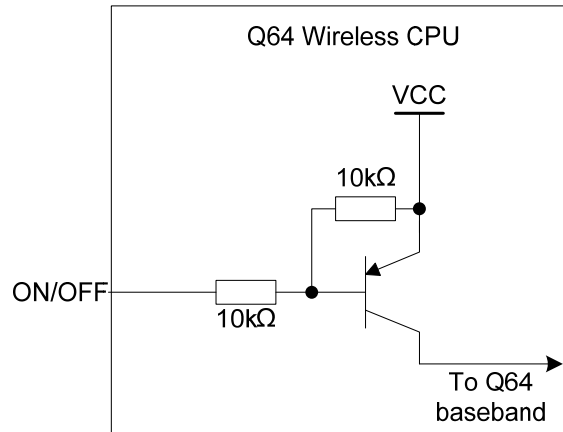


Figure 29: ON/OFF circuitry inside Q64

3.14.3 Application

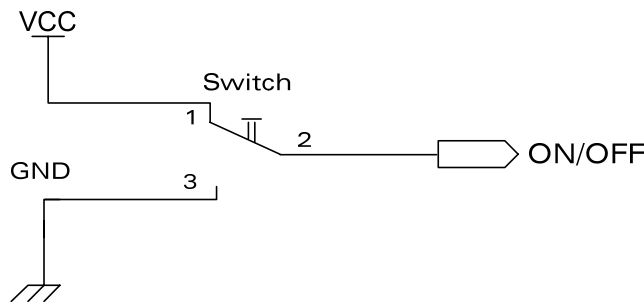


Figure 30: Example of ON/OFF pin connection

3.14.3.1 Power-ON

Whatever the Q64 has embedded GR plug-in or not, once the Wireless CPU® is powered, the application must set the ON/OFF signal to low to start the Wireless CPU® power-ON sequence. The ON/OFF signal must be held low during a minimum delay of $T_{on/off-hold}$ (Minimum hold delay on the ON/OFF signal) to power-ON. After this delay, an internal mechanism maintains the Q64 in power-ON condition.

During the power-ON sequence, an internal reset is automatically performed by the Wireless CPU® for 40ms (typically). During this phase, any external reset should be avoided.

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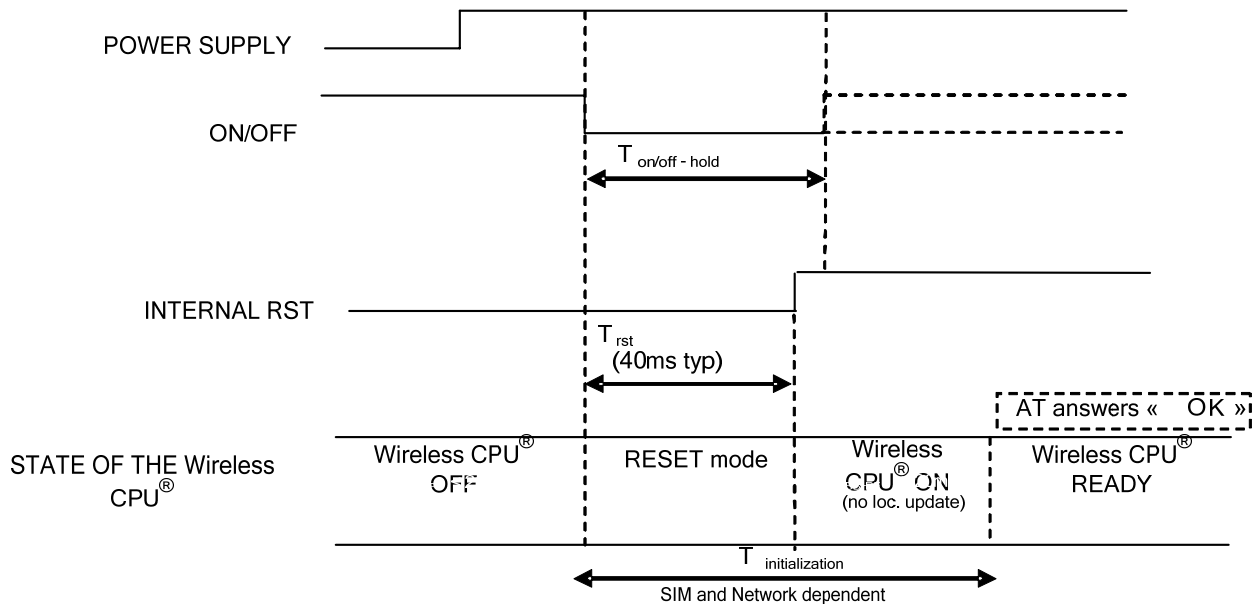


Figure 31 : Power-ON sequence (no PIN code activated)

The duration of the firmware power-up sequence depends on:

- the need to perform a recovery sequence if the power has been lost during a flash memory modification.

Other factors have a minor influence

- the number of parameters stored in EEPROM by the AT commands received so far
- the deterioration of hardware components, especially the flash memory
- the temperature conditions

The *recommended* way to de-assert the ON/OFF signal is to use either an AT command or WIND indicators: the application has to detect the end of the power-up initialization and de-assert ON/OFF afterwards.

- Send an "AT" command and wait for the "OK" answer: once the initialization is complete the AT interface answers « OK » to "AT" message¹.
- Wait for the "+WIND: 3" message: after initialization, the Wireless CPU®, if configured to do so, will return an unsolicited "+WIND: 3" message. The generation of this message is enabled or disabled via an AT command.

Note:

- Please refer to the document [4] AT Command Interface Guide for Open AT® Firmware v6.5 for more information on these commands.

¹ If the application manages hardware flow control, the AT command can be sent during the initialisation phase.

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Proceeding thus by software detection will always prevent the application from de-asserting the ON/OFF signal too early.

If WIND indicators are disabled or AT commands unavailable or not used, it is still possible to de-assert ON/OFF after a delay long enough ($T_{on/off\text{-}hold}$) to ensure that the firmware has already completed its power-up initialization.

The table below gives the minimum values of $T_{on/off\text{-}hold}$:

$T_{on/off\text{-}hold}$ minimum values

Open AT® Firmware	$T_{on/off\text{-}hold}$
	Safe evaluations of the firmware power-up time
6.65 & above	8 s

The above figure refers to the worst cases: power-loss recovery operations, slow flash memory operations in high temperature conditions, and so on. But they are safe because they are long enough to ensure that ON/OFF is not de-asserted too early.

Additional notes:

1. Typical power-up initialization time figures for best cases conditions (no power-loss recovery, fast and new flash memory...) approximate 3.5 seconds in every firmware version. But setting ON/OFF after this delay does not guarantee that the application will actually start-up if for example the power plug has been pulled off during a flash memory operation, like a phone book entry update or an AT&W command...
2. The ON/OFF signal can be left at a low level until switch OFF. But this is not recommended as it will prevent the AT+CPOF command from performing a clean power-off. (see also Note in section 3.14.3.2 Power-OFF for an alternate usage)
3. When using a battery as power source, it is not recommended to let this signal low:

If the battery voltage is too low and the ON/OFF signal is at high level, an internal mechanism switches OFF the Wireless CPU®. This automatic process prevents the battery from being discharged and optimize its life span.
4. During the power-ON sequence, an internal reset is automatically performed by the Wireless CPU® for 40 ms (typically). Any external reset should be avoided during this phase.
5. Connecting a charger on the Wireless CPU® has exactly the same effect than setting the ON/OFF signal; the Wireless CPU® will not Power-OFF after the AT+CPOF command, unless the charger is disconnected.

3.14.3.2 Power-OFF

In Q64 Wireless CPU® without GR plug-in embedded, to power-OFF the Wireless CPU® correctly, the application must set the ON/OFF signal to high level and then send the AT+CPOF command to de-register from the network and switch OFF the Wireless CPU®.

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Once the "OK" response is issued by the Wireless CPU®, the power supply can be switched off.

If GR plug-in is used, a level transition from high level to low level can be acted as a command to de-register from the network and enable the power-OFF sequence. And then the application must set the ON/OFF signal to high level in order to power-OFF the Q64 Wireless CPU® correctly.

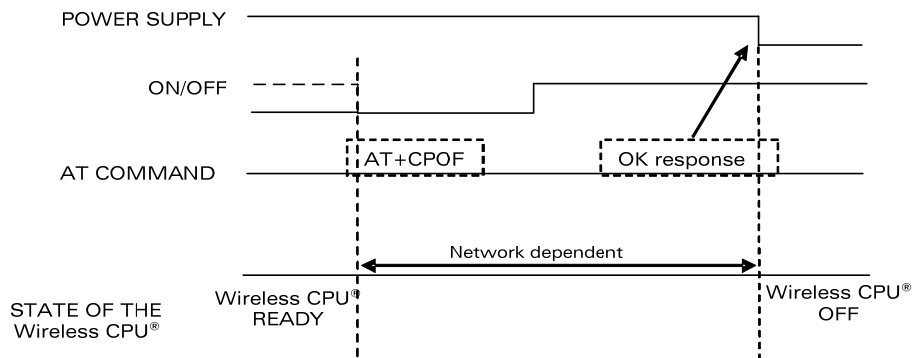


Figure 32: Power-OFF sequence without GR plug-in in Q64

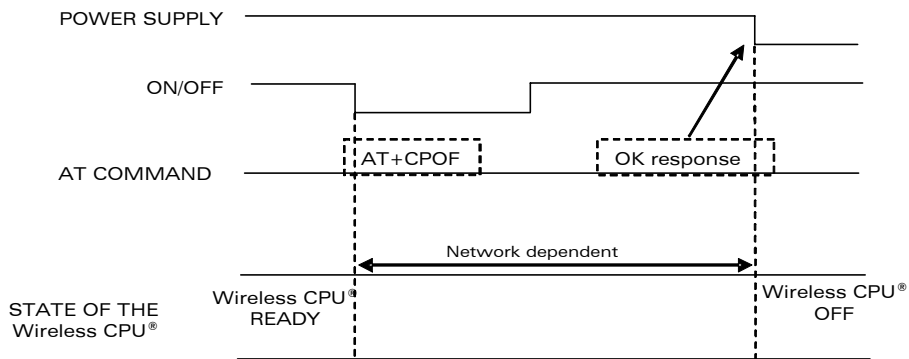


Figure 33: Power-OFF sequence with GR plug-in in Q64

Note:

- If the ON/OFF pin is maintained to ON (Low Level), then the Wireless CPU® cannot be switched OFF.

3.15 SERVICE Signal

A specific control pin SERVICE is available to download the Q64 only if the standard XMODEM download, controlled by AT command, is not possible.

Specific PC software, provided by Wavecom, is needed to perform this download, especially when downloading for the first time the Flash memory.

3.15.1 Features

The SERVICE pin must be connected to the VCC for this specific download.

Electrical characteristics of the signal

Parameter	I/O type	Minimum	Maximum	Unit
V _{IL}	CMOS		0.5	V

BOOT	Operating mode	Comment
0	Normal use	No download
0	Download XMODEM	AT command for Download AT+WDWL
1	Download specific	Need WAVECOM PC software

This SERVICE pin must be at low level for normal use or XMODEM download. The ON/OFF pin must be in low level during downloading.

However, in order to make development and maintenance phases easier, it is **highly recommended** to add a test point, a jumper or a switch to VCC power supply.

Electrical characteristics of the signal

Singal	Parameter	Minimum	Typ	Maximum	Unit
SERVICE	Input voltage	1.5		VCC	V

3.15.2 Pin Description

Signal	Pin number	I/O	I/O type	Description
SERVICE	58	I	-	Download mode selection

3.15.3 Application

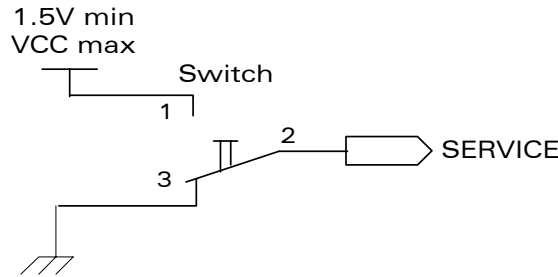


Figure 34: Example of SERVICE pin implementation

3.16 VREF Output

VREF output can be used only for pull-up resistor and can be used as a reference supply.

This voltage supply is available when the Q64 is on.

3.16.1 Features

Electrical characteristics of the signals

Parameter		Minimum	Typ	Maximum	Unit
VREF	Output voltage	2.74	2.8	2.86	V
	Output current			15	mA

3.16.2 Pin Description

Signal	Pin number	I/O	I/O type	Description
VREF	34	O	Supply	Digital supply

3.16.3 Application

Those digital power supplies are mainly used to:

- pull-up signals such as I/O
- supply the digital transistors driving LEDs

Act as a voltage reference for ADC interface ADIN

3.17 VRTC (Backup Battery)

The Q64 Wireless CPU® provides an input / output to connect a Real Time Clock power supply.

3.17.1 Features

This pin is used as a back-up power supply for the internal Real Time Clock. The RTC is supported by the Wireless CPU® when VCC is available, but a back-up power supply is needed to save date and hour when the VCC is switched off.

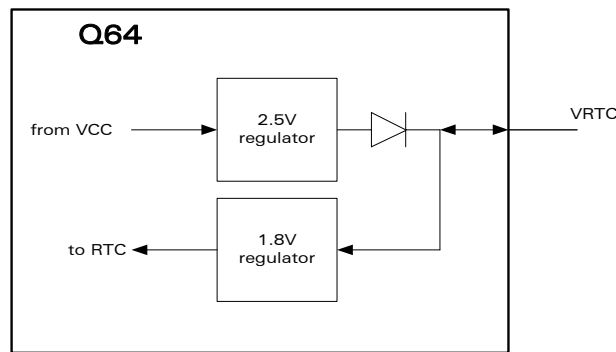


Figure 35 : Real Time Clock power supply

If the RTC is not used, the pin can be left open.

If the VCC is available, the back-up battery can be charged by the internal 2.5V power supply regulator.

Electrical characteristics of the signal

Parameter	Minimum	Typ	Maximum	Unit
Input voltage	1.85		2.5	V
Input current consumption*		3.3		μA
Output voltage		2.45		V
Output current			2	mA

*Provided by a RTC back-up battery when Q64 is off and VCC = 0V.

3.17.2 Pin Description

Signal	Pin number	I/O	I/O type	Description
VRTC	25	I/O	Supply	RTC Back-up supply

3.17.3 Application

Back-up Power Supply can be provided by:

- A super capacitor
- A non rechargeable battery
- A rechargeable battery cell.

3.17.3.1 Super Capacitor

Super Capacitor

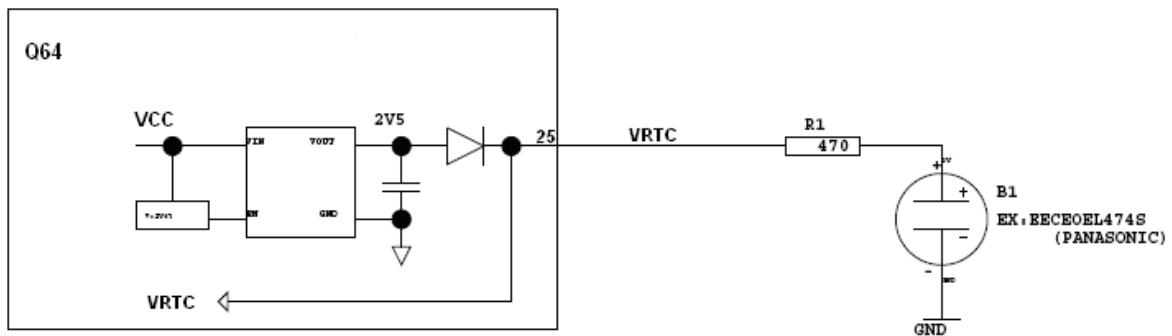


Figure 36: RTC supplied by a gold capacitor

Estimated range with 0.47 Farad Gold Cap: 25 minutes minimum.

Note: The Gold Capacitor maximum voltage is 2.5V.

3.17.3.2 Non Rechargeable battery

Non rechargeable battery cell

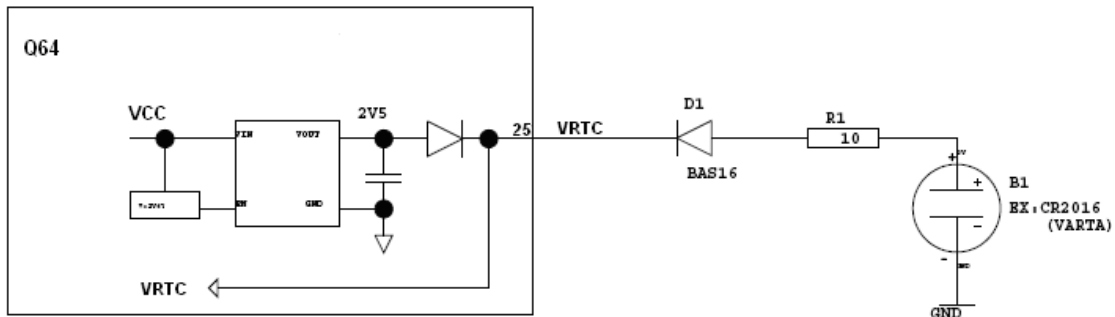


Figure 37: RTC supplied by a non rechargeable battery

The diode D1 is mandatory to avoid damaging the non rechargeable battery.
Estimated range with 85 mAh battery: 800 h minimum.

3.17.3.3 Rechargeable Battery Cell

Rechargeable battery cell

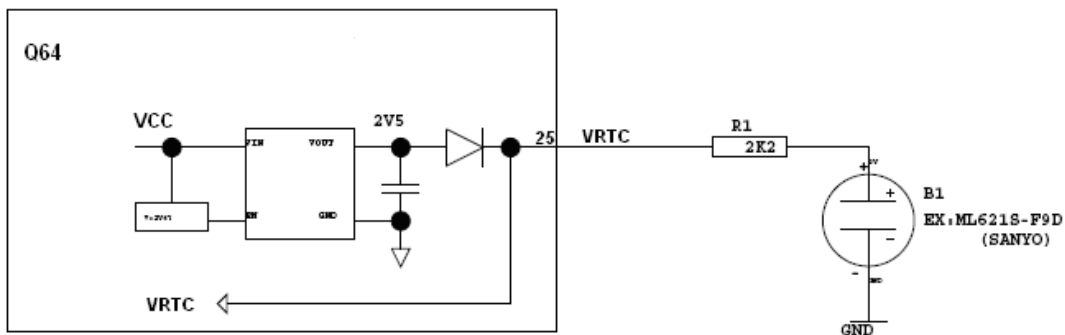


Figure 38: RTC supplied by a rechargeable battery cell

Estimated range with 2 mAh rechargeable battery: ~15 hours.

Warning:

Before assembling the battery cell, ensure that cell voltage is lower than 2.5V to avoid any damage to the Wireless Microprocessor®.

3.18 LED Signal

3.18.1 Features

LED is an open collector output from a PNP transistor. The user must implement some form of transistor circuit to drive the LED.

When the Q64 is ON, this output is used to indicate the network status.

LED status

Q64 state	VCC status	LED status	Q64 status
Q64 ON	VCC > 3.2V	Permanent	Q64 switched ON, not registered on the network
		Slow flash LED ON for 200 ms, OFF for 2 s	Q64 switched ON, registered on the network
		Quick flash LED ON for 200 ms, OFF for 600 ms	Q64 switched ON, registered on the network, communication in progress
		Very quick flash LED ON for 100ms, OFF for 200ms	Q64 switched on, software downloaded is either corrupted or non-compatible ("BAD SOFTWARE")

Electrical characteristics of the signal

Parameter	Condition	Minimum	Typ	Maximum	Unit
V _{OH}			2.8		V
I _{OUT}			7		mA

The LED state is high during the RESET time and undefined during the software initialization time. During software initialization time, during 2 seconds max after RESET cancellation, the LED signal is toggling and it does not provide the Q64 status. After 2 seconds, the LED provides the true status of the Wireless CPU®.

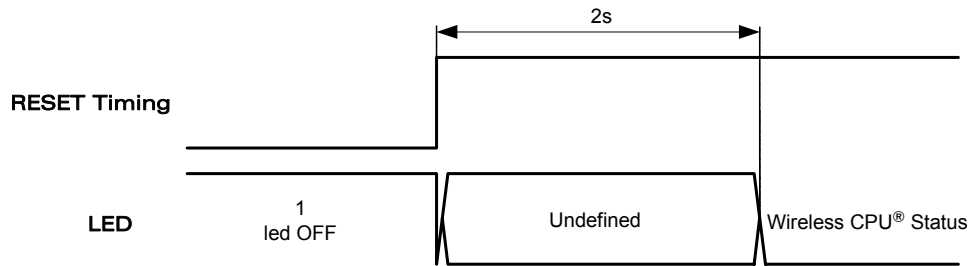


Figure 39 : LED state during RESET and Initialization time

3.18.2 Pin Description

Signal	Pin number	I/O	I/O type	Reset state	Description
LED	33	O	Open-Collector	1 *	LED driving

* This signal is undefined 2 seconds after the reset (initialization time).

3.18.3 Application

The GSM activity status indication signals LED (pin 33) can be used to drive a Light Emitter Diode (LED). This signal is an open-collector from a PNP digital transistor according to the Q64 activity status.

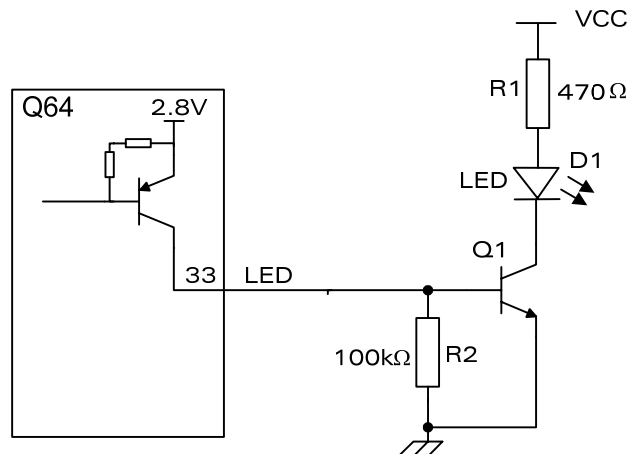


Figure 40: Example of GSM activity status implementation

A NPN transistor Q1 is used for driving the LED.

R1 value can be harmonized depending on the LED (D1) characteristics.

R2 is **MANDATORY** and should be implemented on the application side for the LED flashing.

3.19 Digital Audio Interface (PCM)

The Digital audio interface (PCM) interface mode allows the connectivity with audio standard peripherals. It can be used, for example, to connect an external audio codec. The programmability of this mode allows to address a large range of audio peripherals.

3.19.1 Features

- IOM-2 compatible device on physical level
- Master mode only with 6 slots by frame, user only on slot 0
- Bit rate single clock mode at 768KHz only
- 16 bits data word MSB first only
- Linear Law only (no compression law)
- Long Frame Synchronization only
- Push pull configuration on PCM-OUT and PCM-IN

The digital audio interface configuration cannot be different from the specified features above.

AC characteristics

Signal	Description	Minimum	Typ	Maximum	Unit
T _{sync_low} + T _{sync_high}	PCM-SYNC period		125		μs
T _{sync_low}	PCM-SYNC low time		93		μs
T _{sync_high}	PCM-SYNC high time		32		μs
T _{SYNC-CLK}	PCM-SYNC to PCM-CLK time		-154		ns
T _{CLK-cycle}	PCM-CLK period		1302		ns
T _{IN-setup}	PCM-IN setup time	50			ns
T _{IN-hold}	PCM-IN hold time	50			ns
T _{OUT-delay}	PCM-OUT delay time			20	ns

PCM interface consists of 4 wires:

- **PCM-SYNC** (output): The frame synchronization signal delivers an 8 kHz frequency pulse that synchronizes the frame data in and the frame data out.
- **PCM-CLK** (output): The frame bit clock signal controls the data transfer with the audio peripheral.

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- **PCM-OUT** (output): The frame "data out" depends on the selected configuration mode.
- **PCM-IN** (input): The frame "data in" is depends on the selected configuration mode.

The PCM-IN signal should be in Hz out of user slot.

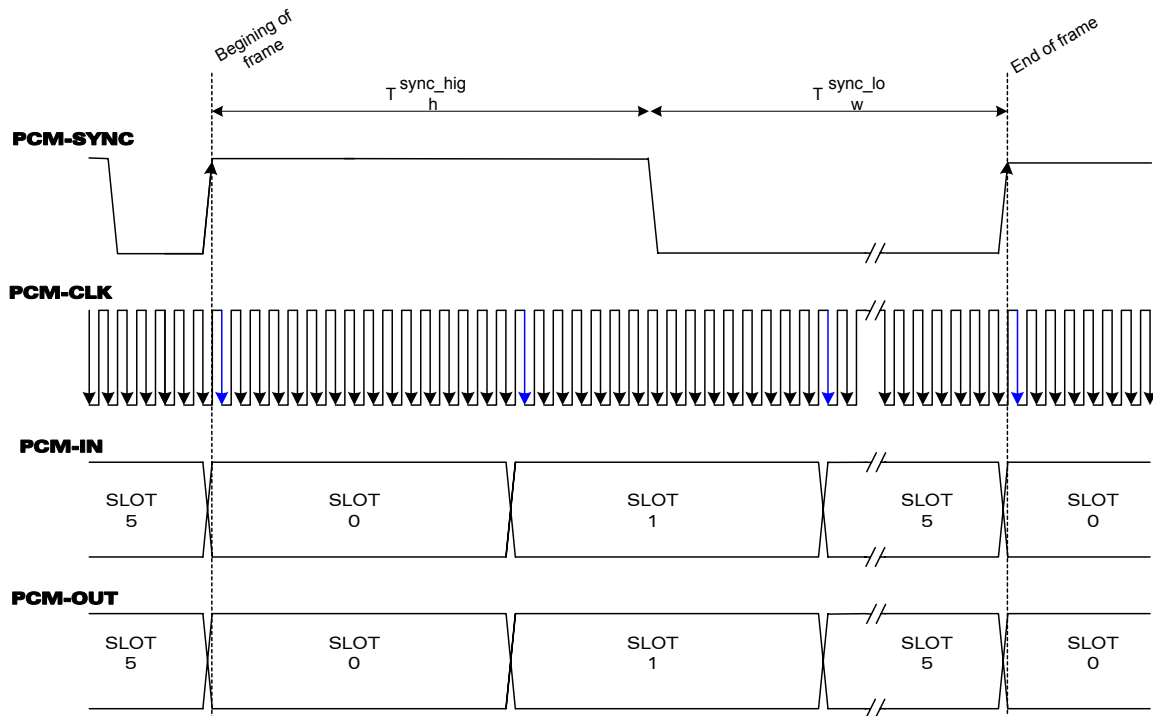


Figure 41 : PCM Frame waveform

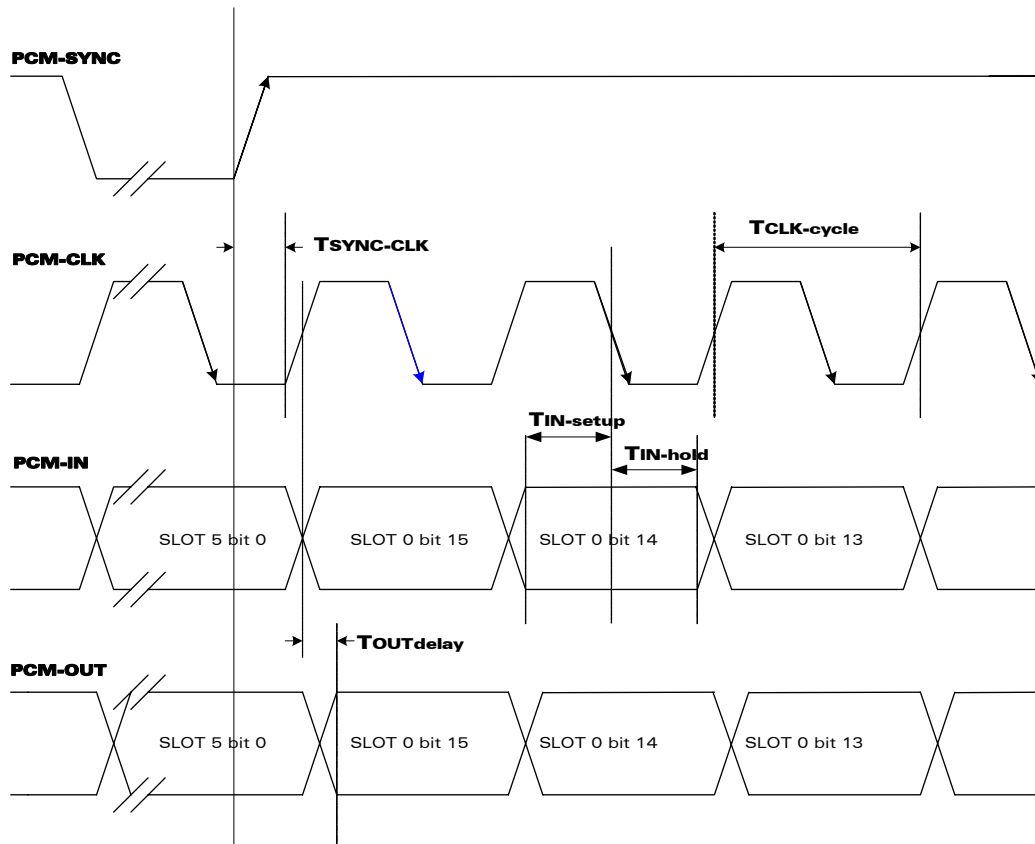


Figure 42 : PCM Sampling waveform

3.19.2 Pin Description

Signal	Pin number	I/O	I/O type	Reset state	Description
PCM-SYNC	51	O	2V8	Undefined	Frame synchronization 8Khz
PCM-CLK	52	O	2V8	Undefined	Data clock
PCM-OUT	48	O	2V8	Undefined	Data output
PCM-IN	47	I	2V8	Undefined	Data input

See chapter 3.4, "Electrical Information for Digital I/O" on page 30 for 2V8-1, 2V8-2, pull-up and open drain voltage characteristics and for Reset state definition.

3.20 USB 2.0 Interface

A 4-wire USB slave interface is available which complies with USB 2.0 protocol signaling. But it is not compliant with the electrical interface, due to the 5V of VUSB.

The USB interface signals are VUSB, USBDP, USBDN and GND.

3.20.1 Features

- 12Mbit/s full speed transfer rate
- 3.3V typ. compatible
- USB Soft connect feature
- Download feature is not supported by USB
- CDC 1.1 – ACM compliant

Electrical characteristics of the signals

Parameter	Min	Typ	Max	Unit
VUSB, USBDP, USBDN	3	3.3	3.6	V
VUSB Input current consumption		8		mA

Note:

A 5V to 3.3V typ. voltage regulator is needed between the external interface power in line (+5V) and the Q64 line (VUSB).

3.20.2 Pin Description

Signal	Pin number	I/O	I/O type	Description	Multiplexed with
VUSB	49	I	VUSB	USB Power Supply	Not mux
USBDP	45	I/O	VUSB	Differential data interface positive	Not mux
USBDN	46	I/O	VUSB	Differential data interface negative	Not mux

3.20.3 Application

A typical schematic is shown below:

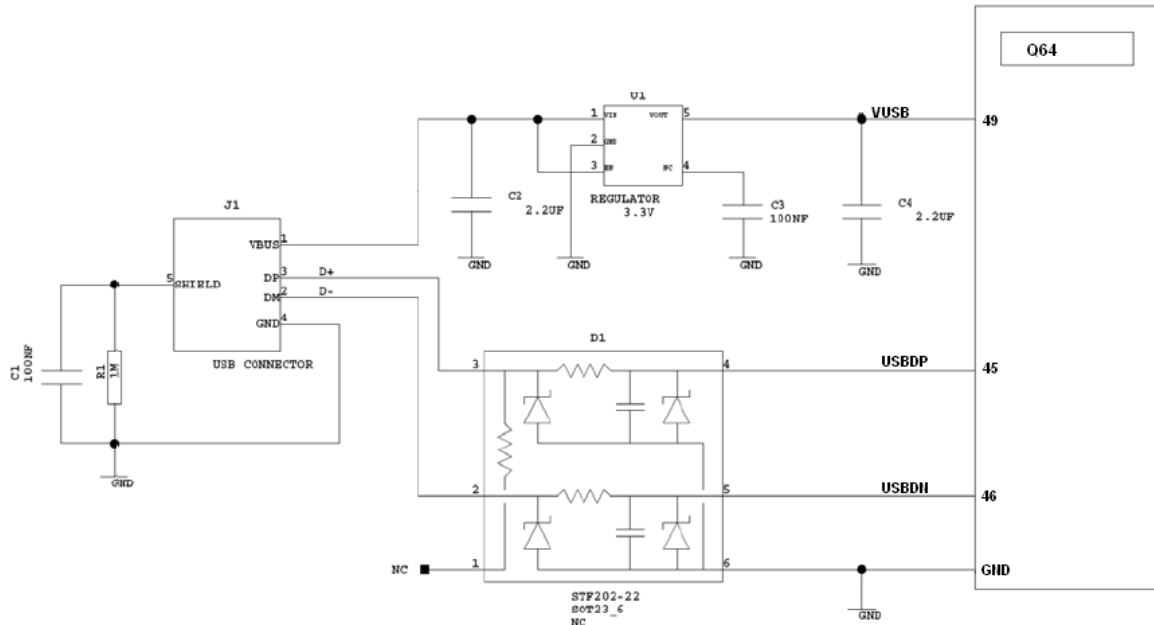


Figure 43: Example of USB implementation

Recommended components:

- R1: 1MΩ
- C1, C3 : 100nF
- C2, C4 : 2.2μF
- D1 : STF2002-22 from SEMTECH
- U1 : LP2985AIM 3.3V from NATIONAL SEMICONDUCTOR

The regulator used is a 3.3V one. It is supplied through J1 when the USB wire is plugged.

The EMI/RFI filter with ESD protection is D1. The D1 integrated pull up resistor used to detect full speed is not connected as it is embedded in the Wireless CPU®.

R1 and C1 must be close to J1.

3.21 RF Interface

The Wireless CPU®s antenna connector allows transmission of radio frequency (RF) signals from the Wireless CPU® to an external customer supplied antenna. The connector is a micro-miniature coaxial MMCX through hole-mounted socket. A number of suitable MMCX type, mating plugs are available from the following manufacturers:

- Amphenol
- Suhner
- IMS Connector Systems

The nominal impedance of the antenna interface is 50 Ω.

3.21.1 RF Connection

Notes:

- The Q64 does not tolerate an antenna switch for a car kit. But this function can be implemented externally and can be driven by using a GPIO.
- The antenna cable and connector should be selected in order to minimize losses in frequency bands used for GSM 850/900MHz and 1800/1900MHz.

3.21.2 RF Performances

RF performances are compliant with the ETSI recommendation GSM 05.05.

The main parameters for Receiver are:

- GSM850 Reference Sensitivity = -108 dBm Static & TUHigh
- E-GSM900 Reference Sensitivity = -108 dBm Static & TUHigh
- DCS1800 Reference Sensitivity = -107 dBm Static & TUHigh
- PCS1900 Reference Sensitivity = -107 dBm Static & TUHigh
- Selectivity @ 200 kHz : > +9 dBc
- Selectivity @ 400 kHz : > +41 dBc
- Linear dynamic range: 63 dB
- Co-channel rejection: >= 9 dBc

And for Transmitter:

- Maximum output power (EGSM & GSM850): 33 dBm +/- 2 dB at ambient temperature
- Maximum output power (GSM1800 & PCS1900): 30 dBm +/- 2 dB at ambient temperature
- Minimum output power (EGSM & GSM850): 5 dBm +/- 5 dB at ambient temperature
- Minimum output power (GSM1800 & PCS1900): 0 dBm +/- 5 dB at ambient temperature

3.21.3 Antenna Specifications

The antenna must fulfill the following requirements:

- The optimum operating frequency depends on the application. A dual-band or a quad-band antenna will work in these frequency bands and have the following characteristics:

Characteristic	Q64			
	E-GSM 900	DCS 1800	GSM 850	PCS 1900
TX Frequency	880 to 915 MHz	1710 to 1785 MHz	824 to 849 MHz	1850 to 1910 MHz
RX Frequency	925 to 960 MHz	1805 to 1880 MHz	869 to 894 MHz	1930 to 1990 MHz
Impedance	50 Ω			
VSWR	Rx max	1.5 :1		
	Tx max	1.5 :1		
Typical radiated gain	0dBi in one direction at least			

Warning:

Wavecom strongly recommends working with an antenna manufacturer either to develop an antenna adapted to the application or to adapt an existing solution to the application.

Both mechanical and electrical antenna adaptations are key issues in the design of the GSM terminal.

4 Consumption Measurement Procedure

This chapter describes the procedure for consumption measurement which is used to obtain the Wireless CPU® consumption specification.

Q64/OASS1.0 consumption specification values are measured for all operating modes available on this product. See the appendix of document [4] AT Command Interface Guide for Open AT® Firmware v6.5.

Consumption results are highly dependent on the hardware configuration used during measurement, this chapter describes the hardware configuration settings that should be used to obtain optimum consumption measurements.

4.1 Hardware Configuration

The hardware configuration includes the measurement equipment and the Wireless CPU® with its motherboard.

4.1.1 Equipment

Four devices are used to perform consumption measurement:

- A communication tester
- A current measuring power supply
- A standalone power supply
- A computer, to control the Wireless CPU® and save measurement data.

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Consumption Measurement Procedure

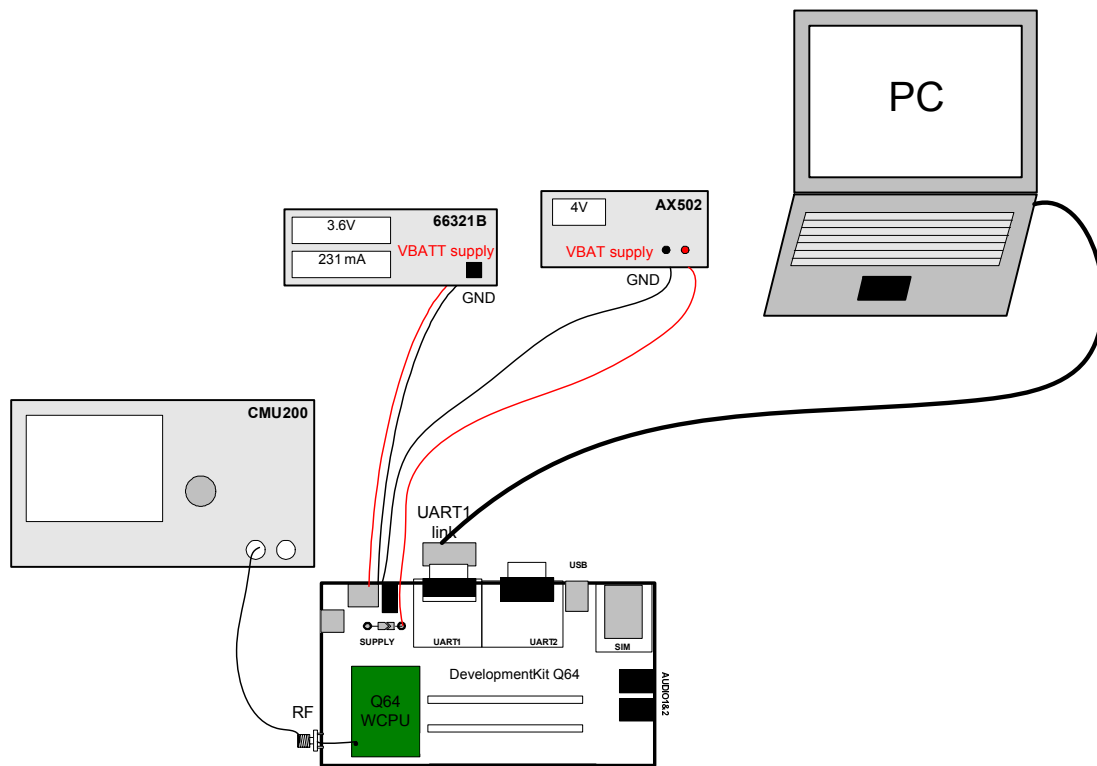


Figure 44: Typical hardware configuration

The communication tester is a **CMU 200** from **Rhode & Schwartz**. This tester offers all required GSM/GPRS network configurations and allows a wide range of network configurations to be set.

The **AX502** standalone power supply is used to supply all motherboard components except the Wireless CPU®. The goal is to separate motherboard consumption from Wireless CPU® consumption, which is measured by the other power supply, the **66321B** “current measuring power supply”.

The “current measuring power supply” is also connected and controlled by the computer (GPIB control not shown in the previous figure).

A SIM must be inserted in the Q64 Wireless CPU® Development Kit during all consumption measurements.

Equipment reference list:

Device	Manufacturer	Reference	
Communication Tester	Rhode & Schwartz	CMU 200	Quad Band GSM/DCS/GPRS
Current measuring power supply	Agilent	66321B	Used for VBATT (for WMP alone)
Stand alone power supply	Metrix	AX502	Used for VBAT (for boards peripherals)

Product Technical Specification & Customer Design Guidelines Consumption Measurement Procedure

4.1.2 Wireless CPU® Development Kit

The Wireless CPU® board used is the Q64 Wireless CPU® Development board. This board can be used to perform consumption measurement with several settings.

The Wireless CPU® is only powered by VBATT on the development board. The Development Kit board is powered by the standalone power supply at VBAT. It is for this reason that the link between VBATT and VBAT (J103) must be opened (by removing the solder at the top of board in the SUPPLY area).

- VBATT powered by the current measuring power supply (**66321B**).
- VBAT powered by the standalone power supply (**AX502**).

The R100, R101 resistor, and D101, D103 diode (around the BAT-TEMP connector) must be removed.

The UART2 link is not used, therefore J501, J503 must be opened (by removing the solder).

The "LED" should not be used, so R103 and R104 resistors must be removed.

The USB link is not used, therefore J801, J802 and J803 must be opened (by removing the solder).

Around "CONFIG" area, the switch SERVICE must be to OFF position.

The purpose of the settings is to eliminate all bias current from VBATT and to supply the entire board (except the Wireless CPU) via VBAT only.

The standalone power supply may be set to 4 volts.

4.1.3 SIM cards used

Consumption measurement may be performed with 3-Volt or 1.8-Volt SIM cards. However, all specified consumption values are for a 3-Volt SIM card.

Caution: The SIM card is supplied by the Wireless CPU®, consumption measurement results may vary depending on the SIM card.

4.2 Software Configurations

Software configuration for the equipment and Wireless CPU® settings.

4.2.1 Wireless CPU® Configuration

The Wireless CPU® software configuration is simply performed by selecting the operating mode to be used to perform the measurement.

A description of the operating modes and the procedure used to change operating mode are given in the appendix of document [4] AT Command Interface Guide for Open AT® Firmware v6.5.

Product Technical Specification & Customer Design Guidelines Consumption Measurement Procedure

An overview of the Q64 operating modes is given below:

- Alarm Mode
- Fast Idle Mode
- Slow Idle Mode
- Fast Standby Mode
- Slow Standby Mode
- Connected Mode
- Transfer Mode class 8 (4Rx/1Tx) (in GPRS mode)
- Transfer Mode class 10 (3Rx/2Tx) (in GPRS mode)

NOTE: To enter fast standby mode or slow standby mode, the ON/OFF pin must be kept at low level.

**Product Technical Specification & Customer Design Guidelines
Consumption Measurement Procedure**

4.2.2 Equipment Configuration

The communication tester is set according to the Wireless CPU® operating mode.

Paging during idle modes, Tx burst power, RF band and GSM/DCS/GPRS may be selected on the communication tester.

Network analyzer configuration according to operating mode:

Operating mode		Communication tester configuration	
Alarm Mode		N/A	
Fast Idle Mode		Paging 9 (Rx burst occurrence ~2s)	
		Paging 2 (Rx burst occurrence ~0,5s)	
Slow Idle Mode		Paging 9 (Rx burst occurrence ~2s)	
		Paging 2 (Rx burst occurrence ~0,5s)	
Fast Standby Mode		N/A	
Slow Standby Mode		N/A	
Connected Mode		850/900 MHz	PCL5 (TX power 33dBm)
			PCL19 (TX power 5dBm)
		1800/1900 MHz	PCL0 (TX power 30dBm)
			PCL15 (TX power 0dBm)
GPRS	Transfer Mode class 8 (4Rx/1Tx)	850/900 MHz	Gam.3 (TX power 33dBm)
			Gam.17 (TX power 5dBm)
		1800/1900 MHz	Gam.3 (TX power 30dBm)
			Gam.18 (TX power 0dBm)
	Transfer Mode class 10 (3Rx/2Tx)	850/900 MHz	Gam.3 (TX power 33dBm)
			Gam.17 (TX power 5dBm)
		1800/1900 MHz	Gam.3 (TX power 30dBm)
			Gam.18 (TX power 0dBm)
		1800/1900 MHz	Gam.5 (TX power 26dBm)
			Gam.18 (TX power 0dBm)

The standalone power supply may be set from 3.2V to 4.5V.

The power supply (VCC) used for measurement may be set from 3.2V to 4.8V according to the Wireless CPU® VCC specifications.

Product Technical Specification & Customer Design Guidelines
Consumption Measurement Procedure

4.3 Template

This template may be used for consumption measurement, all modes and configurations are available.

Three VCC voltages are measured, 3.2V, 3.6V and 4.8V and the minimum/maximum RF transmission power configurations are set and measured.

Power consumption								
Operating mode	Parameters		I _{MIN} average VCC=4,8V	I _{NOM} average VCC=3,6V	I _{MAX} average VCC=3,2V	I _{MAX} peak	unit	
Alarm Mode							µA	
Fast Idle Mode	Paging 9 (Rx burst occurrence ~2s)						mA	
	Paging 2 (Rx burst occurrence ~0,5s)						mA	
Slow Idle Mode	Paging 9 (Rx burst occurrence ~2s)						mA	
	Paging 2 (Rx burst occurrence ~0,5s)						mA	
Fast Standby Mode							mA	
Slow Standby Mode							mA	
Connected Mode	850/900 MHz	PCL5 (TX power 33dBm)					mA	
		PCL19 (TX power 5dBm)					mA	
	1800/1900 MHz	PCL0 (TX power 30dBm)					mA	
		PCL15 (TX power 0dBm)					mA	
GPRS	Transfer Mode class 8 (4Rx/1Tx)	850/900 MHz	Gam.3 (TX power 33dBm)				mA	
			Gam.17 (TX power 5dBm)				mA	
		1800/1900 MHz	Gam.3 (TX power 30dBm)					mA
			Gam.18 (TX power 0dBm)					mA
	Transfer Mode class 10 (3Rx/2Tx)	850/900 MHz	Gam.3 (TX power 33dBm)				mA	
			Gam.17 (TX power 5dBm)				mA	
		1800/1900 MHz	Gam.3 (TX power 30dBm)					mA
			Gam.18 (TX power 0dBm)					mA
			Gam.18 (TX power 0dBm)					mA
			Gam.18 (TX power 0dBm)					mA

5 Technical Specifications

5.1 General Purpose Connector Pin-out Description

Description	I/O*	Voltage	Signal Name		Pin Number		Signal Name		Voltage	I/O*	Description
			Mux	Nominal	Nominal	Mux					
Power Supply	I	VCC		VCC	1	2	GND		GND		Ground
Power Supply	I	VCC		VCC	3	4	GND		GND		Ground
Power Supply	I	VCC		VCC	5	6	GND		GND		Ground
Power Supply	I	VCC		VCC	7	8	GND		GND		Ground
Power Supply	I	VCC		VCC	9	10	GND		GND		Ground
Charger input	I	CHG_IN		CHG_IN	11	12	GND		GND		Ground
Analog to Digital converter 4	I	Analog	GPIO5	ADIN4 / GPIO5	13	14	ON/OFF		VCC	I	ON / OFF Control
SIM Power Supply	O	1V8 or 3V		SIMVCC	15	16	SIMDET		1V8	I	SIM Detection
SIM reset Output	O	1V8 or 3V		SIMRST	17	18	SIMDAT		1V8 or 3V	I/O	SIM Data
SIM Clock	O	1V8 or 3V		SIMCLK	19	20	GPIO15		2V8-1	I/O	General Purpose Input Output
General Purpose Input Output	I/O	2V8-1		GPIO1	21	22	GPIO2		2V8-1	I/O	General Purpose Input Output
General Purpose Input Output	I/O	2V8-1		GPIO3	23	24	GPIO4		2V8-1	I/O	General Purpose Input Output
Power Supply	I/O	VRTC		VRTC	25	26	ADIN1 / BAT-TEMP		Analog	I	Analog to Digital converter 1
Analog to Digital converter 2	I	Analog		ADIN2	27	28	ADIN3		Analog	I	Analog to Digital converter 3
I ² C serial data	I/O	Pull-up		SDA	29	30	SCL		Pull-up	I/O	I ² C serial clock
Buzzer Output	O	Open drain		BUZZER	31	32	DSR1 / GPIO7	GPIO7	2V8-1	O	Main RS232 Data Set Ready
Flash Led Output or GPIO	O or IO	Open Collector or 2V8-1	GPIO6	LED / GPIO6	33	34	VREF		2V8-1	O	2.8V Supply Output
General Purpose Input Output	I/O	2V8-1		GPIO16	35	36	RI / GPIO8	GPIO8	2V8-1	O	Main RS232 Ring Indicator
Main RS232 Data Terminal Ready	I	2V8-1	GPIO10	DTR1 / GPIO10	37	38	DCD1 / GPIO11	GPIO11	2V8-1	O	Main RS232 Data Carrier Detect

Product Technical Specification & Customer Design Guidelines
Technical Specifications

Description	I/O*	Voltage	Signal Name		Pin Number		Signal Name		Voltage	I/O*	Description
			Mux	Nominal			Nominal	Mux			
Main RS232 Request To Send	I	2V8-1	GPIO9	RTS1 / GPIO9	39	40	CTS1 / GPIO12	GPIO12	2V8-1	O	Main RS232 Clear To Send
Main RS232 Transmit	I	2V8-1	GPIO18	DTM1 / GPIO18	41	42	DFM1 / GPIO17	GPIO17	2V8-1	O	Main RS232 Receive
Auxiliary RS232 Transmit	I	2V8-2		DTM3	43	44	DFM3		2V8-2	O	Auxiliary RS232 Receive
USB Data	I/O	VUSB		USBDP	45	46	USBDN		VUSB	I/O	USB Data
PCM Data Input	I	2V8-2		PCM-IN	47	48	PCM-OUT		2V8-2	O	PCM Data Output
USB Power supply input	I	VUSB		VUSB	49	50	Reserved				
PCM Frame Synchro	O	2V8-2		PCM-SYNC	51	52	PCM-CLK		2V8-2	O	PCM Clock
Microphone Input Positive	I	Analog		MIC1P	53	54	MIC1N		Analog	I	Microphone Input Negative
Earpiece 1 Output Positive	O	Analog		EARP	55	56	EARN		Analog	O	Earpiece 1 Output Negative
Auxiliary Audio Output	O	Analog		AUXO	57	58	SERVICE		VCC	I	Not Used
Auxiliary Audio Input	I	Analog		AUXI	59	60	AREF		GND		Analog Ground

* The I/O direction information is concerning only the nominal signal. When the signal is configured in GPIO, it is always either an Input or an Output.

5.2 Environmental Specifications

Wavecom specifies following temperature range of Q64 product.

The Q64 is compliant with following operating class:

Conditions	Temperature range
Operating / Class A	-20 °C to +55°C
Operating / Class B	-30 °C to +75°C
Storage	-40 °C to +85°C

Function Status Classification:

Class A:

The Q64 will have full function during and after an external influence. The GSM performance will meet the minimum ETSI requirements.

Class B:

Any function can be out of specified tolerances. All functions will be automatically going back to normal tolerances after that the external influences are removed. Performance is allowed to exceed the minimum ETSI requirements, but it must be possible to connect a call and send an SMS.

Product Technical Specification & Customer Design Guidelines
Technical Specifications

Q64		ENVIRONNEMENTAL CLASSES		
TYPE OF TEST	STANDARDS	STORAGE Class 1.2	TRANSPORTATION Class 2.3	OPERATING (PORT USE) Class 7.3
Cold	IEC 68-2.1 Ab test	-25° C 72 h	-40° C 72 h	-20° C (GSM900) 16 h -10° C (GSM1800/1900) 16h
Dry heat	IEC 68-2.2 Bb test	+70° C 72 h	+70° C 72 h	+55° C 16 h
Change of temperature	IEC 68-2.14 Na/Nb test		-40° / +30° C 5 cycles t1 = 3 h	-20° / +30° C (GSM900) 3 cycles -10° / +30° C (GSM1800/1900); 3 cycles t1 = 3 h
Damp heat cyclic	IEC 68-2.30 Db test	+30° C 2 cycles 90% - 100% RH variant 1	+40° C 2 cycles 90% - 100% RH variant 1	+40° C 2 cycles 90% - 100% RH variant 1
Damp heat	IEC 68-2.56 Cb test	+30° C 4 days	+40° C 4 days	+40° C 4 days
Sinusoidal vibration	IEC 68-2.6 Fc test	5 - 62 Hz : 5 mm / s 62 - 200Hz : 2 m / s2 3 x 5 sweep cycles		
Random vibration wide band	IEC 68-3.36 Fdb test		5 - 20 Hz : 0.96 m2 / s3 20 - 500Hz : - 3 dB / oct 3 x 10 min	10 - 12 Hz : 0.96 m2 / s3 12 - 150Hz : - 3 dB / oct 3 x 30 min

Figure 45 : Environmental classes

5.3 Reflow Soldering

The Wireless CPU® Q64 does not support any reflow soldering.

5.4 Mechanical Specifications

5.4.1 Physical Characteristics

The Q64 has a complete self-contained shield.

- Overall dimensions : 50 x 33 x 6.8 mm
- Weight : 11.6 g

5.4.2 Mechanical Drawings

The next page provides mechanical specifications of the Q64.

Product Technical Specification & Customer Design Guidelines
Technical Specifications

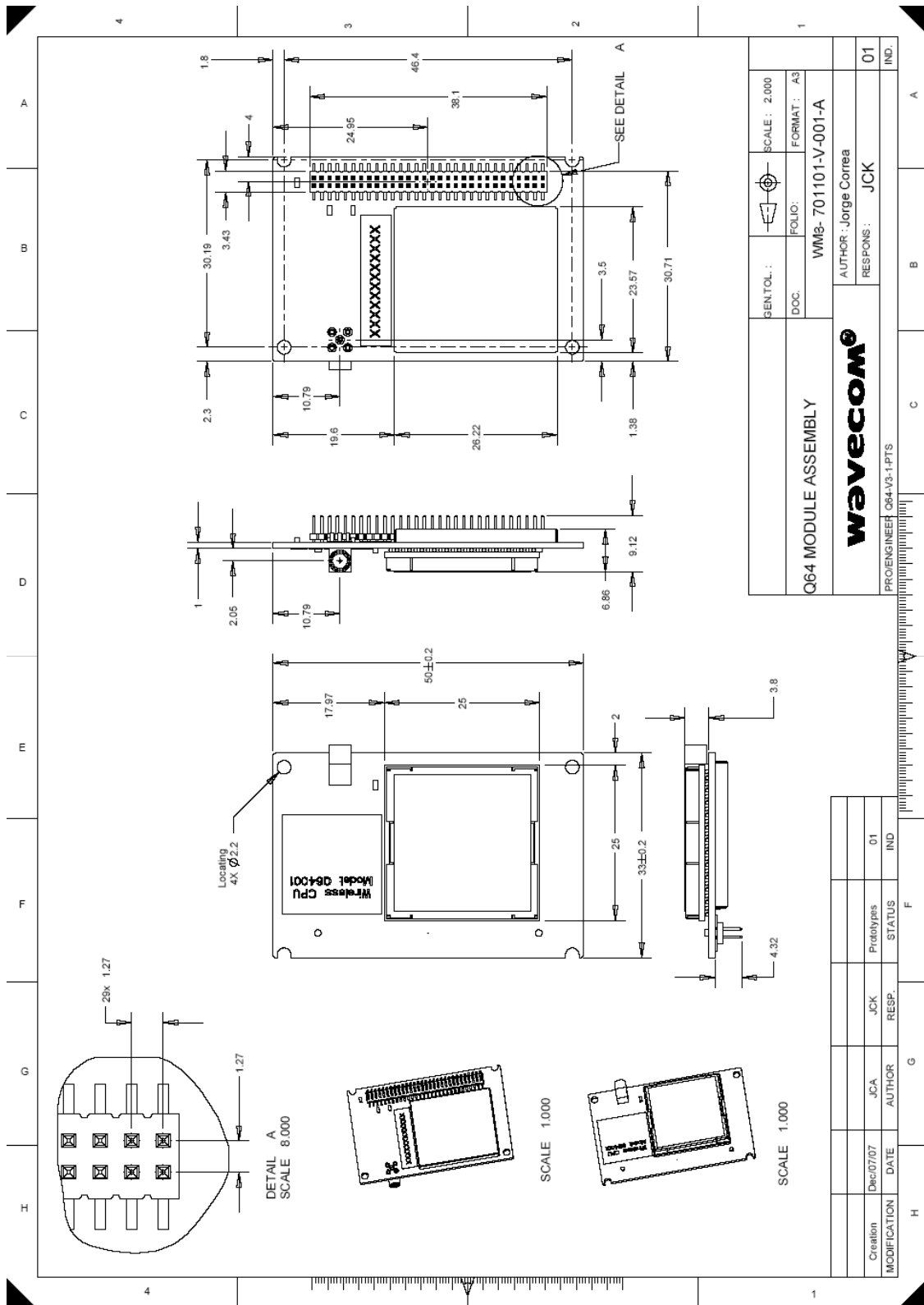


Figure 46 : Mechanical drawing

6 Connector Peripheral Devices References

6.1 General Purpose Connector

The GPC is a 60-pin connector with standard 0.05 in (1.27 mm) pitch device.

The matting connector has the following reference:

M50-3113042 from HARWIN (see <http://www.harwin.com>)

The stacking height is 4.5 mm.

6.2 SIM Card Reader

- ITT CANNON CCM03 series (see <http://www.ittcannon.com>)
- AMPHENOL C707 series (see <http://www.amphenol.com>)
- JAE (see <http://www.jae.com>)

Drawer type:

- MOLEX 99228-0002 (connector) / MOLEX 91236-0002 (holder) (see <http://www.molex.com>)

6.3 Microphone

Possible suppliers:

- HOSIDEN
- PANASONIC
- PEIKER

6.4 Speaker

Possible suppliers:

- SANYO
- HOSIDEN
- PRIMO
- PHILIPS

6.5 Antenna Adaptor

The following antenna MMCX to SMA adaptors can be used for a SMA antenna connection in application side.

- RADIALL R191398020 MMCX MALE STRAIGHT ADAPTER (<http://www.radiall.com>)
- Amphenol 242141 SMA Jack/MMCX Plug (<http://www.amphenol.com>)

6.6 Antenna Cable

The following 50Ω MMCX to SMA cable reference has been qualified for being plugged on Q64:

- OnlineCables.com FXC1F061C-4 SMA Female Bulkhead (<http://www.onlinecables.com>)

6.7 GSM Antenna

GSM antennas and support for antenna adaptation can be obtained from manufacturers such as:

- ALLGON (<http://www.allgon.com>)
- IRSCHMANN (<http://www.hirschmann.com/>)

7 Noises and Design

7.1 Hardware and RF

7.1.1 EMC Recommendations

The EMC tests have to be performed as soon as possible on the application to detect any possible problem.

When designing, special attention should be paid to:

- Possible spurious emission radiated by the application to the RF receiver in the receiver band
- ESD protection **is mandatory** on all signals which have external accessibility (typically human accessibility).
 - Typically, ESD protection is mandatory for the:
 - SIM (if accessible from outside)
- EMC protection on audio input/output (filters against 900MHz emissions)
- Biasing of the microphone inputs
- Length of the SIM interface lines (preferably <10cm)
- Ground plane: WAVECOM recommends having a common ground plane for analog / digital / RF grounds and connecting to AREF (pin 60) for the audio grounding.
- Metallic case or plastic casing with conductive paint are recommended

Note:

The Wireless CPU® does not include any protection against overvoltage.

7.1.2 Power Supply

The power supply is one of the key issues in the design of a GSM terminal.

A weak power supply design could affect in particular:

- EMC performances.
- the emissions spectrum
- the phase error and frequency error

Warning:

Careful attention should be paid to:

- **Quality of the power supply: low ripple, PFM or PSM systems should be avoided (PWM converter preferred).**

- Capacity to deliver high current peaks in a short time (pulsed radio emission).

7.1.3 Layout Requirement

Four sets of screws, nuts, washer and standoffs are recommended to hold the Wireless CPU® tightly on the application board.

- Nut, 2-56 Hex
- Screw, 2-56, 1/2" Length
- Stand-offs, 2-56, .156" O.D., 1/4" Length
- Washer, 2-56 Lock Inside Tooth

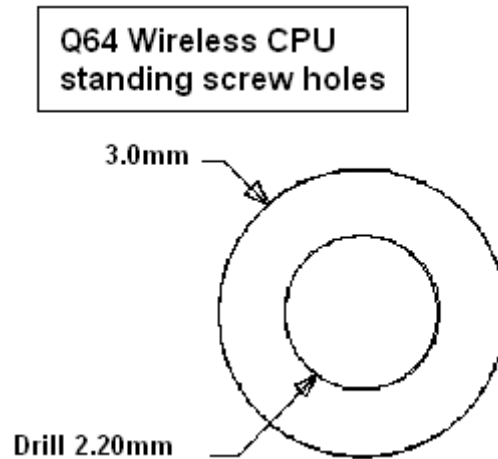


Figure 47: Standing screw holes requirement

7.1.4 Antenna

Warning:

Wavecom strongly recommends to work with an antenna manufacturer either to develop an antenna adapted to the application or to adapt an existing solution to the application.

Both mechanical and electrical antenna adaptation are key issues in the design of the GSM terminal.

7.2 Mechanical Integration

Attention should be paid to:

- Antenna cable integration (bending, length, position, etc.)

7.3 Operating System Upgrade

The Q64 Wireless CPU® Operating System is stored in flash memory and can be easily upgraded.

IMPORTANT:

In order to follow regular changes in the GPRS standard and to offer a state-of-the-art Operating System, Wavecom recommends that the application designed around a Wireless CPU® (or Wireless CPU® based product) allow easy Operating System upgrades on the Wireless CPU® via the standard X-modem protocol. Therefore, the application shall either allow a direct access to the Wireless CPU® serial link through an external connector or implement any mechanism allowing the Wireless CPU® Operating System to be downloaded via X-modem.

The Operating System file can be downloaded onto the modem using the X-modem protocol. The AT+WDWL command allows the download process to be launched (see the description in the AT Command User Guide, [4] AT Command Interface Guide for Open AT® Firmware v6.5).

The serial signals required to proceed with X-modem downloading are:

- DTM1, DFM1, RTS1, CTS1 and GND.

The Operating System file can also be downloaded onto the modem using the DOTA (download over the air) feature. This feature is available with the Open AT® interface. For more details, please, refer to the Open AT® documentation, [4] AT Command Interface Guide for Open AT® Firmware v6.5.

8 Appendix

8.1 Standards and Recommendations

GSM ETSI, 3GPP, GCF and NAPRD03 recommendations for Phase II.

Specification Reference	Title
3GPP TS 45.005 v5.5.0 (2002-08) Release 5	Technical Specification Group GSM/EDGE. Radio Access Network; Radio transmission and reception
GSM 02.07 V8.0.0 (1999-07)	Digital cellular telecommunications system (Phase 2+); Mobile Stations (MS) features (GSM 02.07 version 8.0.0 Release 1999)
GSM 02.60 V8.1.0 (1999-07)	Digital cellular telecommunications system (Phase 2+); General Packet Radio Service (GPRS); Service description, Stage 1 (GSM 02.60 version 8.1.0 Release 1999)
GSM 03.60 V7.9.0 (2002-09)	Technical Specification Group Services and System Aspects; Digital cellular telecommunications system (Phase 2+); General Packet Radio Service (GPRS); Service description; Stage 2 (Release 1998)
3GPP TS 43.064 V5.0.0 (2002-04)	Technical Specification Group GERAN; Digital cellular telecommunications system (Phase 2+); General Packet Radio Service (GPRS); Overall description of the GPRS radio interface; Stage 2 (Release 5)
3GPP TS 03.22 V8.7.0 (2002-08)	Technical Specification Group GSM/EDGE. Radio Access Network; Functions related to Mobile Station (MS) in idle mode and group receive mode; (Release 1999)
3GPP TS 03.40 V7.5.0 (2001-12)	Technical Specification Group Terminals; Technical realization of the Short Message Service (SMS) (Release 1998)
3GPP TS 03.41 V7.4.0 (2000-09)	Technical Specification Group Terminals; Technical realization of Cell Broadcast Service (CBS) (Release 1998)
ETSI EN 300 903 V8.1.1 (2000-11)	Digital cellular telecommunications system (Phase 2+); Transmission planning aspects of the speech service in the GSM Public Land Mobile Network (PLMN) system (GSM 03.50 version 8.1.1 Release 1999)

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Specification Reference	Title
3GPP TS 04.06 V8.2.1 (2002-05)	Technical Specification Group GSM/EDGE Radio Access Network; Mobile Station - Base Station System (MS - BSS) interface; Data Link (DL) layer specification (Release 1999)
3GPP TS 04.08 V7.18.0 (2002-09)	Technical Specification Group Core Network; Digital cellular telecommunications system (Phase 2+); Mobile radio interface layer 3 specification (Release 1998)
3GPP TS 04.10 V7.1.0 (2001-12)	Technical Specification Group Core Networks; Mobile radio interface layer 3 Supplementary services specification; General aspects (Release 1998)
3GPP TS 04.11 V7.1.0 (2000-09)	Technical Specification Group Core Network; Digital cellular telecommunications system (Phase 2+); Point-to-Point (PP) Short Message Service (SMS) support on mobile radio interface (Release 1998)
3GPP TS 45.005 v5.5.0 (2002-08)	Technical Specification Group GSM/EDGE. Radio Access Network; Radio transmission and reception (Release 5)
3GPP TS 45.008 V5.8.0 (2002-08)	Technical Specification Group GSM/EDGE Radio Access Network; Radio subsystem link control (Release 5)
3GPP TS 45.010 V5.1.0 (2002-08)	Technical Specification Group GSM/EDGE Radio Access Network; Radio subsystem synchronization (Release 5)
3GPP TS 46.010 V5.0.0 (2002-06)	Technical Specification Group Services and System Aspects; Full rate speech; Transcoding (Release 5)
3GPP TS 46.011 V5.0.0 (2002-06)	Technical Specification Group Services and System Aspects; Full rate speech; Substitution and muting of lost frames for full rate speech channels (Release 5)
3GPP TS 46.012 V5.0.0 (2002-06)	Technical Specification Group Services and System Aspects; Full rate speech; Comfort noise aspect for full rate speech traffic channels (Release 5)

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Specification Reference	Title
3GPP TS 46.031 V5.0.0 (2002-06)	Technical Specification Group Services and System Aspects; Full rate speech; Discontinuous Transmission (DTX) for full rate speech traffic channels (Release 5)
3GPP TS 46.032 V5.0.0 (2002-06)	Technical Specification Group Services and System Aspects; Full rate speech; Voice Activity Detector (VAD) for full rate speech traffic channels (Release 5)
TS 100 913V8.0.0 (1999-08)	Digital cellular telecommunications system (Phase 2+); General on Terminal Adaptation Functions (TAF) for Mobile Stations (MS) (GSM 07.01 version 8.0.0 Release 1999)
GSM 09.07 V8.0.0 (1999-08)	Digital cellular telecommunications system (Phase 2+); General requirements on interworking between the Public Land Mobile Network (PLMN) and the Integrated Services Digital Network (ISDN) or Public Switched Telephone Network (PSTN) (GSM 09.07 version 8.0.0 Release 1999)
3GPP TS 51.010-1 v5.0.0 (2002-09)	Technical Specification Group GSM/EDGE; Radio Access Network ;Digital cellular telecommunications system (Phase 2+); Mobile Station (MS) conformance specification; Part 1: Conformance specification (Release 5)
3GPP TS 51.011 V5.0.0 (2001-12)	Technical Specification Group Terminals; Specification of the Subscriber Identity Module - Mobile Equipment (SIM - ME) interface (Release 5)
ETS 300 641 (1998-03)	Digital cellular telecommunications system (Phase 2); Specification of the 3 Volt Subscriber Identity Module - Mobile Equipment (SIM-ME) interface (GSM 11.12 version 4.3.1)
GCF-CC V3.7.1 (2002-08)	Global Certification Forum – Certification criteria
NAPRD03 V2.6.0 (2002-06)	North America Permanent Reference Document for PTCRB tests

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The Wireless CPU® Q64 connected to a development kit board application is certified to be in accordance with the following Rules and Regulations of the Federal Communications Commission (FCC).

Power listed on the Gant is conducted for Part 22 and conducted for Part 24.

This device contains EGSM/GPRS Class 10 functions in the 900 and 1800MHz Band, which are not operational in U.S. Territories.

This device can be used only for mobile and fixed applications. The antenna(s) used for this transmitter must be installed at a distance of minimum 20 cm and must not be co-located or operated with any other antenna or transmitter.

Users and installers must be provided with antenna installation instructions and transmitter operating conditions for satisfying RF exposure compliance.

Antennas used for this OEM module must not exceed 0.9 dBi gain for GSM 850 MHz and 7.1 dBi for GSM 1900 MHz for fixed operating configurations. For mobile operations the gain must not exceed 0.9 dBi for GSM 850 MHz and 3.1 dBi for GSM 1900 MHz. This device is approved as a module to be installed in other devices.

Installed in portable devices, the RF exposure condition requires a separate mandatory equipment authorization for the final device.

The license module will have a FCC ID label on the module itself. The FCC ID label should be clearly seen through a window or must be visible when an access panel, door or cover is easily removed.

If not, a second label must be placed on the outside of the device that contains the following text: FCC ID: O9EWMP100

This device complies with Part 15 of the FCC Rules. Operation is subjected to the following conditions:

- This device may not cause harmful interference.
- This device must accept any interference received, including interference that may cause undesired operation.

IMPORTANT: Manufacturers of mobile or fixed devices incorporating Q64 Wireless CPU® are advised to:

- clarify any regulatory question,
- have their completed product tested,
- have product approved for FCC compliance, and
- include instructions according to above mentioned RF exposure statements in end product user manual.

Please note that changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

8.2 Safety Recommendations (For Information Only)

IMPORTANT
FOR THE EFFICIENT AND SAFE OPERATION OF YOUR GSM APPLICATION
BASED ON WMP100
PLEASE READ THIS INFORMATION CAREFULLY

8.2.1 RF Safety

8.2.1.1 General

Your GSM terminal is based on the GSM standard for cellular technology. The GSM standard is spread all over the world. It covers Europe, Asia and some American and African regions. This is the most used telecommunication standard.

Your GSM terminal is actually a low power radio transmitter and receiver. It sends out and receives radio frequency energy. When you use your GSM application, the cellular system which handles your calls, controls the radio frequency and the power level of your cellular modem.

8.2.1.2 Exposure to RF Energy

There has been some public concern about possible health effects of using GSM terminals. Although research on health effects from RF energy has focused on the current RF technology for many years, scientists have conducted research regarding newer radio technologies, such as GSM. After existing research had been reviewed, and after compliance to all applicable safety standards had been tested, it has been concluded that the product was fitted for use.

If you are concerned about exposure to RF energy there are things you can do to minimize exposure. Obviously, limiting the duration of your calls will reduce your exposure to RF energy. In addition, you can reduce RF exposure by operating your cellular terminal efficiently by following the guidelines described below.

8.2.1.3 Efficient Terminal Operation

To operate your GSM terminal at the lowest power level, and still have satisfactory call quality:

If your terminal has an extendible antenna, extend it fully. Some models allow you to place a call with the antenna retracted. However your GSM terminal operates more efficiently with the antenna fully extended.

Do not hold the antenna when the terminal is « IN USE ». Holding the antenna affects call quality and may cause the modem to operate at a higher power level than needed.

8.2.1.4 Antenna Care and Replacement

Do not use the GSM terminal with a damaged antenna. If skin contact occurs with a damaged antenna, a minor burn may result. Replace a damaged antenna immediately. Consult your manual to see if you may change the antenna yourself. If so, use only a manufacturer-approved antenna. Otherwise, have your antenna repaired by a qualified technician.

Use only the supplied or approved antenna. Unauthorized antennas, modifications or attachments could damage the terminal and may contravene local RF emission regulations or invalidate type approval.

8.2.2 General Safety

8.2.2.1 Driving

Check the laws and the regulations regarding the use of cellular devices in the area where you have to drive as you always have to comply with them. When using your GSM terminal while driving, please:

- give full attention to driving,
- pull off the road and park before making or answering a call if driving conditions require to do so.

8.2.2.2 Electronic Devices

Most electronic equipment, for example in hospitals and motor vehicles is shielded from RF energy. However RF energy may affect some improperly shielded electronic equipment.

8.2.2.3 Vehicle Electronic Equipment

Check your vehicle manufacturer representative to determine if any on-board electronic equipment is adequately shielded from RF energy.

8.2.2.4 Medical Electronic Equipment

Contact the manufacturer of any personal medical device (such as pacemakers, hearing aids) to determine if they are adequately shielded from external RF energy.

Turn your terminal **OFF** in health care facilities when any regulation posted in the area instruct you to do so. Hospitals or health care facilities may be using RF monitoring equipment.

8.2.2.5 Aircraft

Turn your terminal OFF before boarding any aircraft.

- Use it on the ground only with crew permission.
- Do not use it in the air.

To prevent possible interference with aircraft systems, Federal Aviation Administration (FAA) regulations require you to have permission from a crew member to use your terminal while the aircraft is on the ground. To prevent interference with cellular systems, local RF regulations prohibit using your modem while airborne.

8.2.2.6 Children

Do not allow children to play with your GSM terminal. It is not a toy. Children could hurt themselves or others (by poking themselves or others in the eye with the antenna, for example). Children could damage the modem, or make calls that increase your modem bills.

8.2.2.7 Blasting Areas

To avoid interfering with blasting operations, turn your unit OFF when in a « blasting area » or in areas posted: « turn off two-way radio ». Construction crews often use remote control RF devices to set off explosives.

8.2.2.8 Potentially Explosive Atmospheres

Turn your terminal **OFF** while in any area with a potentially explosive atmosphere. It is rare, but your application or its accessories could generate sparks. Sparks in such areas could cause a burst or fire resulting in bodily injuries or even death.

Areas with a potentially explosive atmosphere are often, but not always, clearly marked. They include fuelling areas such as petrol stations; below decks on boats; fuel or chemical transfer or storage facilities; and areas where the air contains chemicals or particles, such as grain, dust, or metal powders.

Do not carry or store flammable gas, liquid, or explosives, in the compartment of your vehicle which contains your terminal or accessories.

Before using your terminal in a vehicle powered by liquefied petroleum gas (such as propane or butane) ensure that the vehicle complies with the relevant fire and safety regulations of the country in which the vehicle is to be used.

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